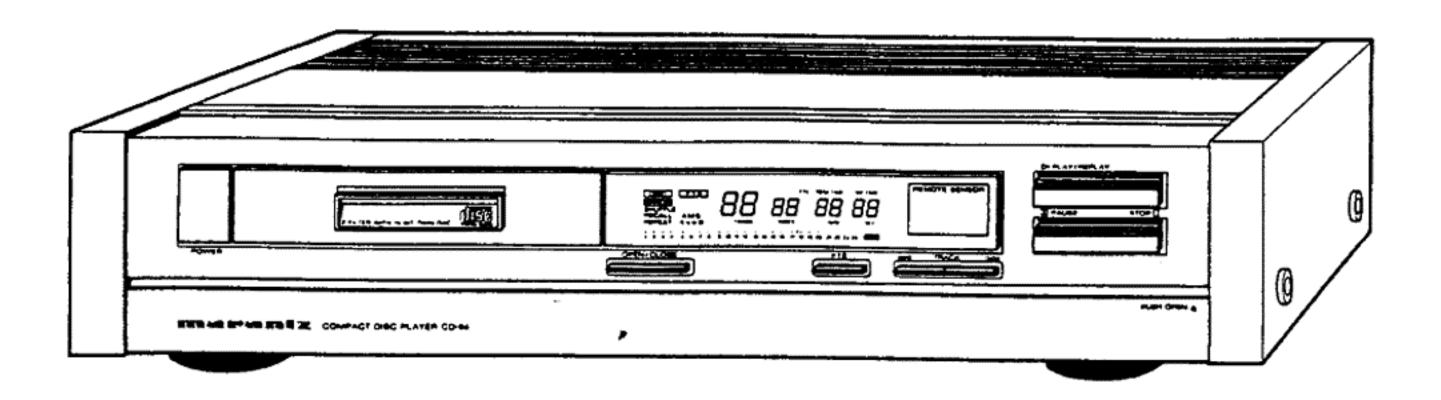


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MODEL CD-94 COMPACT DISC PLAYER



INTRODUCTION

This service manual was prepared for use by Authorized Warranty Stations and contains service information for the Marantz Model CD-94 Compact Disc Player.

Servicing information and voltage data included in this manual are intended for use by knowledgeable and experienced personnel only. All instructions should be read carefully. No attempt should be made to proceed without a good understanding of circuitry operation.

The parts list furnishes complete ordering information. Most replacement parts should be ordered from the Marantz Company. However, a simple description is included for parts which can be obtained locally.

How to use this service manual

- The "Common parts" which Marantz Japan, Inc. has established are eliminated from this service manual.
- These "Common parts" are applied to all models in the service manuals arranged and issued by MJI.
- To indicate clearly the common parts in the schematic diagram, a line is drawn above or under the Ref. Desig. No. of applicable parts.
- "Common parts" can be supplied from the Marantz service center as ever.
 In case of ordering, please establish the parts number of 10 figures following the procedure mentioned in this service manual "How to establish the parts number for common parts".

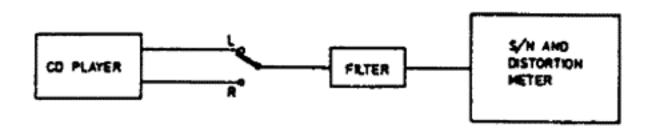
(NOTE)

When you order parts to the Marantz parts center, please take notice of the following points.

- 1) Please correctly write the parts number of 10 figures following the rule.
- Since ordering parts by the Ref. Desig. No. or ratings indicated in the schematic diagram does not satisfy the above conditions, the Marantz parts supply system does not work properly.
 - As this case is apt to cause a trouble, please pay attention to it.

ELECTRICAL MEASUREMENTS AND ADJUSTMENTS

Specification measurement



To measure the specification use can be made of audio test disc 4822 397 30085.

Use a 7th order filter, e.g. 4822 395 30204 (see Figure), to measure:

- Total harmonic distortion (THD).
- Intermodulation distortion.
- Signal-to-noise (S/N).

Laser power supply (POS. VOLT. SH.)

For check and preliminary adjustment of the laser supply see service manual C.D.M.-1.

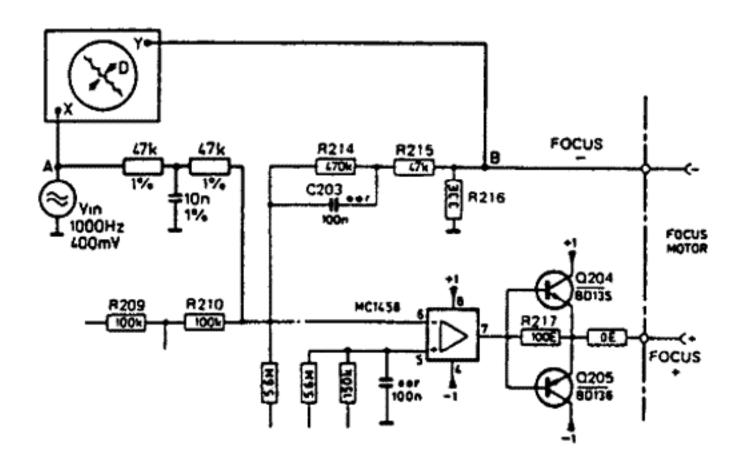
Adjusting the laser supply

Play track 1 of test disc 4822 397 300096 (disc without defects).

Connect a DC voltmeter across resistor R309 on the servo PCB (= on emitter of transistor Q315 and ground).

Adjust the laser power supply with resistor 3180 until the voltage across resistor R309 is 575 ± 75 mV.

Adjusting the focus bandwidth



Make a measuring arrangement according to the figure.

Play track 1 of test disc 4822 397 30096 (disc without defects).

Adjust trimming resistor 3158 on PRE. AMPL + LASER PCB for a 180° phase difference between signals A and B. This corresponds with a minimum distance D in the Lissajous pattern.

R=47 kΩ - 1% 5322 116 54671 C=10 nF -1% 5322 121 54154

Check of the AGC and offset circuits

(See SERVO PCB)

Play track 1 of test disc 4822 397 80096 (Disc without defects).

The voltage between pin 7 of IC Q303 (4/4) and \pm should be -4 V \pm 2 V.

The voltage between pin 8 of IC Q302 (2/4) and \pm should be 0 V \pm 2 V.

INITIATION OF THE SERVICING PROGRAMME OF THE μP

- Servicing position "0"

Simultaneously depress the STOP, PLAY and SEARCH >> buttons. Keep these three buttons depressed while the mains voltage is switched on. This is the STAND-BY mode, "0" appears on the display.

In this state it is possible to move the arm by means of the SEARCH FORW and SEARCH REV keys with a minimum torque to the outside and the inside resp.

This enables a check of the free motion of the arm across the disc.

Servicing position "1"

From servicing position "0" the player can be brought in servicing position "1" by depressing the NEXT key.

In this state the laser emits light and the objective starts to focus. When the focal point has been reached, "1" appears on the display.

When **no** disc has been inserted the objective goes 16 x to and fro. Then the player reassumes servicing position "0".

As in servicing position "0" the arm can be moved across the diameter of the disc by means of the SEARCH FORW and SEARCH REV keys.

Servicing position "2"

To be reached by depressing the NEXT key after servicing position "1" has been reached.

The turntable motor starts to run

On the display appears "2".

In preparation of the transition to servicing position "3" the arm is sent to the centre of the disc.

- Servicing position "3"

To be reached by depressing the NEXT key after servicing position "2" has been reached.

The radial control is switched on. The subcode information is ignored. MUSB is high so that the music information is released.

On the display appears "3".

(Dependent on the length of the lead-in track music will be reproduced after approx 1 min.)

In this state it is possible to move the arm by means of the SEARCH FORW and the SEARCH REV keys to the outside and to the inside resp. Now the motion is controlled by the μ and the arm moves by steps of 64 tracks as long as the key is depressed.

If one of the servicing positions 1, 2 or 3 is disturbed (e.g. braking or removing the disc) the player reassumes servicing position "0".

The servicing programme can be left by switching the mains switch (POWER ON/OFF) off and on. (Hardware reset).

FAULTFINDING METHOD

Preface

In course of the development of the troubleshooting guide for the Compact Disc it has become clear that a different approach from the one applied so far was required.

For, it is no longer possible to use the classic strategy, i.e. basing the troubleshooting method on a number of possible faults in the unit.

Practice has shown that a certain fault, with the associated symptom, can have a wide variety of causes. The reason is that this player incorporates a number of feedback loop configurations—which, moreover, might affect each other—and this impedes the obvious measurements.

The method below divides the player from diagram point of view into nine clearly distinguishable subgroups and by performing some measurements, the sub-group being in failure can be isolated. Later the defective circuit can be further examined according to the method given.

PRACTICAL HINTS

Test discs

It is important to handle the test discs with great care. For, the troubles (black dots, fingerprints, etc.) are exclusively and unambiguously positioned.

Damage can cause additional drop-outs etc. and as a result the conscious fault on this disc is no longer exclusive.

In that case it is no longer possible to check e.g. whether the track detector is working correctly.

Measurements on op-amps

In the electronic circuits of the servo systems opamps are frequently being applied. These op-amps can be used as amplifiers, as filters, as investors, as buffers, etc.

In those cases where feedback is applied in one way or the other, the voltage difference at the differential inputs inclines to zero. This applies both to DC

and to AC.

The cause can be traced back to the properties of an ideal op-amp $(Z_1=\infty; G=\infty; Z_0=0)$.

In practice this means that it is nearly impossible to perform measurements on the inverting and non-inverting inputs of op-amps if one input is directly connected to ground.

In those cases only the output signal will be measurable.

That is why in most cases no AC voltages can be given to the inputs.

The DC voltages at the inputs are equal.

Stimulating with "0" and "1"

In the troubleshooting method certain pins should in a number of cases be connected to ground or be connected to the power supply voltage.

This way of acting offers the possibility to overrule certain circuits and to stimulate others.

In this way the diagnose time can be reduced.

In a number of cases the relevant pins appear to be op-amp outputs.

In this respect it should be mentioned that the outputs of the used op-amps are short-circuit protected.

This implies that the output of an op-amp can be made low (= usually ground potential) without consequences.

On the other hand should be pointed out that it is **not** allowed to connect the output of an op-amp directly to the power supply voltage.

I/Os of microprocessors should not be connected directly to power supply voltage.

These I/Os are allowed to be brought to "0" in case this is mentioned explicitly.

Selection of ground point

It is very important to select a ground point as close as possible to the test point.

Conditions for injecting

- It is should be pointed out that injection of levels or signals from a strange source is never allowed to occur when the power supply voltage is lacking in the circuit in question.
- Naturally, the injected level is never allowed to exceed the power supply voltage of the circuit in question.

Continuous burning of the laser

in service loop 2.

 Disconnect plug J203 on the servo PCB and connect pin J203-9 (laser) of the cable connector to ground.

Now the focus loop and the radial loop are interrupted as well:

J203-7 (RE1 = Radial Error 1), J203-8 (RE2 = Radial Error 2) and J203-10 (FE = Focus Error).

The laser also burns continuously when the set is

Irregular working of the display

Irregular working of the display when the set is opened and playing, might have been caused by incidental body effect in the region of the crystal oscillators.

Switching "off" and "on" of the mains voltage will eliminate this effect.

Indication of checkpoint

In the circuit diagram the checkpoints have been given a serial number (e.g. (12)), to which the troubleshooting method will refer.

For oscillograms, amplitudes, time bases and position of set, see tables of checkpoints.

GENERAL CHECKPOINTS

In the detailed troubleshooting method following below a number of general conditions, required for proper functioning of the player, will **not** be repeated. Before starting the detailed troubleshooting method these general points should be checked.

- a. Ensure that disc and objective are clean (remove dust, fingerprints, etc.) and use undamaged discs.
- b. Convince yourself of the presence of the clock frequencies, viz.:
 - 12 MHz for μP servo (pin 18)
 - 11.2896 MHz for FILTER-B IC (pin 19)
 - 2.82-5.64 MHz for free-running PLL circuit on the DECODER-A IC (pin 27)
 - 3 MHz for control and display μP (pin 33).
- c. Check whether all power supply voltages are present and have the correct level. See PCB drawings.
- d. Check whether the two mutes (KILL and MUSB are inactive so that data are nowhere interrupted. This should go high about 2 seconds after the mains voltage is switched on.

MUSB=pin 23 of the FILTER-B IC on the decoder PCB.

Normally this pin is high during play and low during search.

DETAILED TROUBLESHOOTING METHOD

A number of quick and efficient checks immediately give a definite answer on poorly functioning sections of the player.

To check the servo systems four service loops have been built in μ P Q271.

Before calling in service loops, it should be checked (position power on) whether the bus (clock, data: pin 17 and 10 or 11 of μ P Q271 resp.) is free. In other words, checking whether these lines do not have a short circuit to ground or supply voltage (level low or "high"). In such a case the buttons cannot be operated.

For troubleshooting the step-by-step method below is followed.

First step (with disc on turntable)

Bring the player in service loop 1 or 2

If one of the conditions for service loop 1 or 2 is not met, the questions below should be answered positively in the sequence given.

In practice this means that when one question has been answered positively, all the preceding circuits, to which the questions refer, are functioning well.

Example: if the eye pattern is present, we may conclude that the laser is working, the laser is in focus and that the turntable motor is running.

Note:

In some situations, certain faults in the radial servo circuit affect the focus servo circuit (e.g. if, supply voltage + 1 of IC Q301 in the radial circuit fails, the focus coil starts oscillating).

To determine if this situation exists, connect point on the servo PCB to ground.

In this way, the influence of the radial servo circuit on the focus servo circuit can be eliminated.

- A. Is the laser giving light? (Test method: see sub A)
- B. Is the angle disc-light pin within the tolerance, i.e 90°± 0.5°? (Test method: see description mentioned in chapter "Mechanical measurements and adjustments" of the C.D.M. manual).
- C. Is the laser giving sufficient light? (Test method: see sub C).
- D. Does the objective come in focus? (Test method: see sub D).
- E. Is the turntable motor running and, if so, is it running at the correct speed? (Test method: see sub E).

If the answers to questions 1 or 2 through E are positive, it should be possible to bring the player in service loop 1 or 2.

Second step (with disc on turntable)

Bring the player in service loop 3.

This means that the eye pattern on point (5) (on the decoder PCB has to be stable, while MSC on point (1) on the servo PCB has to be more stable too). (Test method: see DECODER-A IC)

Note that the set is not only tracking a song in loop 3, but also playing the song, provided the digital circuit is working (however music cannot be hard).

If this does not work, return to service loop 2 and answer the questions below positively in the sequence given.

- F. Are \overline{DO} and HFL detectors functioning? (test method: see sub F)
- G. Is track detector functioning? (test method: see sub G)

H. Is the radial control functioning properly? (test method: see sub H)

If the answers to questions F, G and H are positive, it should be possible to bring the player in service loop 3.

Third step (with disc on turntable)

Note that the set is not only tracking a song in loop 3, but also playing the song, provided the digital circuit is working (music cannot be heard).

If this does not work, return to service loop 3 and answer the question below positively.

- I. Is TL functioning, i.e. polarity of RE? (test method: see sub I)
- J. Is information transmission subcode functioning? (test method: see DECODER-AIC)

Check the Q-channel signals.

If the answers to questions I and J are positive, it should be possible to bring the player in the Play mode.

Fourth step (with disc on turntable)

If no music is heard in position "play" or service loop 3 answer the last question.

K. Is digital decoder circuit functioning according to specification (test method: see II. FILTER-B IC and V. KILL CIRCUIT)

Sub. A. IS THE LASER GIVING LIGHT?

Test method

Bring the player in service loop 1 without placing a disc on the turntable. Now the laser is giving light for an unlimited period of time.

Another method for which the laser gives light during an unlimited period of time and the objective is standing still, is disconnecting plug J203 on the servo PCB and connecting point J203-9 of the cable connector to ground.

In case of power-on the laser should burn. This is checked with the aid of a light-sensitive component which is slightly screened from ambient light.

Hereafter follow some examples:

- a. Connect photosensitive diode type BPW4, code number 4822 12032108, with correct polarity to an analogue multimeter (e.g. PM2412) at range 10 kΩ.
 - If the laser is burning, the meter will give virtually full scale deflection.
- b. Connect LDR, code number 4822 116 10002, to digital multimeter PM2517E. If the laser is burning, the resistance will drop to approx. 8 kΩ.

If the laser is not giving any light, proceed to Annex 1.

Sub. C. IS THE LASER GIVING SUFFICIENT LIGHT?

Test method (Test points on Pre-amp PCB)

- Interrupt the collector of Q203 on the servo PCB or ground-the-side of electrolytic capacitor C201. Disconnect plug J203 on the servo PCB and connect pin J203-9 (laser) of the cable connector to ground.
 - Now the laser should continue to give light while FE, RE1 and RE2 are interrupted.
- Place disc on turntable and switch power on.
- Directly inject with AF generator (Z_i ≤ 600 Ohms) to test point (1) FE a sine-wave signal between 25 and 60 Hz (exact frequency is player-dependent) and 2V_{pp}.
- Select such a frequency that the monitor diodes of the light pin give output signals as indicated on test points (5), (6), (7) and (8). Amplitude 40-80 mV.
- If the amplitude is not sufficient, proceed to Annex
 1.

Sub. D. IS THE OBJECTIVE COMING INTO FOCUS?

Test method

No disc on turntable

Switch power on and actuate Play button.

Now the arm should move inwards. Immediately after that the objective should move two times up-and downwards (this happens during searching of the focusing point).

After this the action will stop.

These actions are software-controlled from the servo μP . If this is not working, check μP servo, end stage focus circuit or focus coil.

With disc on turntable

Quick test procedure:

For a rough check on the working of the focus circuit, proceed as follows:

- place disc on turntable.
- set player in service loop 1.
- remove disc from turntable.
- now examinate if the objective focuses by bringing a reflective object (e.g. mirror) above it.

Detailed test procedure

- Check Q203 (on servo PCB) as follows:
 Check whether FN becomes, with each passage
 - of the nominal focusing low for a short period of time. Only when focusing point FN has been found, FE will be released via Q203 (base will become negative).
 - Check whether base of Q202 is driven low from servo μ P (= FCO). If not, check servo μ P. If so, proceed.
- Test focusing circuit as follows:
 Interrupt the collector of Q203 on the servo PCB and disconnect plug J203 on the servo PCB. Con-

nect pin J203-9 (laser) of the cable connector to ground.

Now the laser is burning continuously, FE has been released and the focus loop has been interrupted at test point (i) (=FE) on servo PCB.

Testing of circuit, between test point (1) and focusing coil

(Test points on servo PCB)

- Directly inject a sine-wave signal of 10 Hz, 2V_{pp}, to test point (1) by means of an AF generator (Z₁ ≤ 600 Ω).
- Check visually whether focusing coil "--" and thus objective too "--" responds.
- Check whether this voltage is 0.6 V_{pp} on test point
 2).
- Čheck whether this voltage is 6 V_{pp} on test point
- Check whether this voltage is 5 V_{pp} on test point

Testing the subchassis (Test points on Pre Amp PCB, injection point on servo PCB)

- Place a disc on the turntable.
- Directly inject to test point (1) a sine-wave signal between 25 Hz and 60 Hz at 2 V_{pp} by means of an AF generator (Z_i ≤ 600 Ω). The exact frequency is player-dependent.
- Select such a frequency that the monitor diodes of the light pin give output signals as indicated on test points (5), (6), (7) and (8).
- Check test points (9), (10, (1) and (12).
- Check test point (13).
- Check test point (1).

Is the same as signal on test point (13) but amplitude is dependent on position of potentiometer 3138.

If all the checks are positive, close focus loop (insert plug J203). Now the focusing circuit should be able to operate. Reconnect transistor Q203.

It should be noted here that the amplitudes on test points (5) through (13) are slightly dependent on the characteristic of the monitor diodes.

Sub. E. IS TURNTABLE MOTOR RUNNING AND, IF SO, IS IT RUNNING AT THE CORRECT SPEED?

Test method (Test points on servo PCB)

- Place disc on turntable and bring set in service loop 2.
- If focusing point is found, check whether FCO is low on point (1).
- If not, check focus circuit sub D.
 - If so, proceed.
- Now only power on, disconnect plug J201 on the servo PCB and check MSC=point (12) of cable connector J201 or point (2) on the decoder PCB.

- If not, check Decoder-A IC (Q501) circuit. If so, proceed.
- Reconnect plug J201, disconnect plug 15 on the preamplifier PCB and inject a DC signal to the cable connector of the motor or directly to the turntable motor.

The turntable motor should be running now.

(A DC voltage of 2,5 V approximately corresponds with the rpm during scanning of the innermost tracks).

In this condition the player should be brought in service loop 2 (depress Stop button while mains voltage is switched on).

If DC < 2.5 V Figure G should be visible on test point (1) (servo PCB).

If DC > 2.5 V Figure H should be visible on test point (1).

If so, check turntable control circuit (circuit from point to turntable motor).

If not, check whether MSC is released by means of SSM at pin 16 of IC Q271.

This connecting plug J201 on the servo PCB and measure on pin 12 of cable connector J201.

If MSC is working now, check circuit around IC Q271.

 Take player out of service loop 2, depress Poweron button and then Play button and check eye pattern on point (s) (on decoder PCB).

To stabilize the eye pattern, bring light pin above tracks by hand, or by briefly (5 s) depressing Fast Forward button.

If eye pattern not point is is not present or unstable, check RF pre amplifier (see Annex IV).

- If eye pattern is correct, proceed.
- Check whether point \$\$ (=HFLS) on the servo PCB is correct in service loop 2 (see Figure Y). If not, check HFLS detector circuit (is circuit between point \$\$ and \$\$). If so, proceed.

Take player out of service loop 2 by depressing the power button.

- Check locking-in of PLL circuit of Decoder-A IC.
 (See CEFM signal pin 27: point (58))
 If PLL is locking-in, proceed.
- Check timing signals on output of Decoder-A IC as indicated in "DECODER-A IC".
 - Is the digital decoder circuit functioning according to specification? If timing signals are correct, proceed.
- If MSC is still not functioning properly, replace the relevant specific digital IC according to the trial and error method with the aid of service IC box.
- MSC has to be present now.

Sub. F. ARE THE DO and HFLS DETECTORS FUNC-TIONING?

Test method (Test points on servo PCB)

1 Starting point is:

HFLS = 1 when spot is exactly on track

HFLS = 0 between tracks (e.g. during track jumping)

 $\overline{DO} = 0$, or $\overline{DO} = 1$ in case of drop-out

 $\overline{DO} = 1$, or $\overline{DO} = 0$ when there is no drop-out.

Approximative method

(applicable in service loop 2)

- Place disc on turntable.
- Bring player in service loop 2.
- Check whether DO (test point s) is not continuously "high". Normally test point s) is "low", however small spikes of approximately 100mV are present in case of scratches on the disc.
- Check HFLS (test point (3)).

Precise method

(can be checked in playing set only)

- Place test disc 5A on turntable. Switch power on and depress Play button.
- Select track no. 10: Check point (§).
 HFLS pulses should be present.
- Select track no. 15: Check point 6.
 DO pulses should be present. With this track the HFLS pulses on point 6. should also be present.
- In case of track jumping HFLS pulses are always present on point \$5.

Sub. G. IS TRACK DETECTOR FUNCTIONING WELL?

Test method (Test points on servo PCB)

Switch off the offset circuit:

Loosen resistor 3315 (at the side where it is in contact with pin 8 of IC Q302).

-Mount a 47 kΩ trimming potentiometer between +1 and -1 supply voltage (for example between pins 4 and 11 of IC Q302). Connect the wiper of the trimming potentiometer to the loose side of resistor 3315.

- Place a disc on the turntable.
- Bring the set in service loop 2.
- Adjust the signal on test point symmetrically round 0V by means of the external 47 kΩ trimming potentiometer. The amplitude of the signal may change during this adjustment.
- Measure F.S on point 36.
 Here too the frequency variation depends on the eccentricity of the disc.
- Check point 60.
- Check point (5). Signal cannot be triggered.
- Check point (2).
- Switch the offset circuit on again.

Sub. H. IS THE RADIAL CONTROL FUNCTIONING PROPERLY?

Attention: The offset circuit (d-multipuller) and the AGC circuit (k-multiplier) are correction circuits. This means that under optimal conditions (new disc, minimum tolerances of components) the set may be working properly even if a fault is preset in offset or AGC circuit.

Test method (Testpoints on servo PCB)

- a. Place disc on turntable.
- b. Switch off AGC circuit (k-multiplier) and switch off offset circuit (d-multiplier).

Method:

Switching off AGC circuit: interconnect points (\$) and (6) of IC Q309.

- Place a disc on the turntable.
- Bring the set in service loop 2.
- Adjust the signal on test point (2) symmetrically round 0V by means of the external 47 kΩ trimming pot. The amplitude of the signal may change during this adjustment.
- c. Bring set in service loop 3.

At this moment there is a high probability that the set is working.

If so, check d and k factor (see Annexes II and III).

If not, proceed.

d. Bring set in service loop 2 and check signal on point ②).

The AC-component has to be 12-14 V symmetrically, around a DC level of zero volt.

If this is correct, proceed to e).

If this is not correct check following testpoints

- ⟨३⟩, ⟨३⟩: value should be 0.7 V_{pp}
- (2): value should be 0.2 Vpp
- (2): value should be 0.25 Vpp
- (26): value should be 20 mVpp
- (2), (2): value should be 800 mVpp

Note:

The frequency variation strongly depends on the eccentricity of the disc.

If points & ÷ & are OK, check point & again.
If & is OK, proceed.

- e. Check point (2) (is RE + 650 Hz).

 Value should be Vpp If so, proceed.

 When the set is in the normal stand-by position 650 Hz at 300 mV is present on point (29).
- f. To check radial output stage, do not use a disc, only power on. Inject on points and an respectively a sine-wave signal of 8 to 10 Hz 3 Vpp. Then the radial motor will go back and forth.

At this moment radial tracking must be possible in service loop 3..

Switch the AGC circuit on again.
 If the original fault symptom is still present proceed

to Annex III:

Check of the k-factor.

Switch the offset circuit on again.
 If the original fault symptom is still present, proceed to Annex II:
 Check of the d-factor.

Sub. I. IS INT FUNCTIONING. O.E. POLARIOTY OF RE? (Measure points on servo PCB)

Test method

Bring player in service loop 3 and measure $\overline{\text{INT}}$ on pin 12 of μP servo IC Q271.

A square-wave voltage (0-5V) should be measured on th is pin. As a result of the frequency variation th is square-wave is hard to trigger.

I DECODER-A IC

• Check the MC signal (pin 17; test point 4)

 In stand-by mode, the MC signal (Motor Control) corresponds to the figure below.

Note:

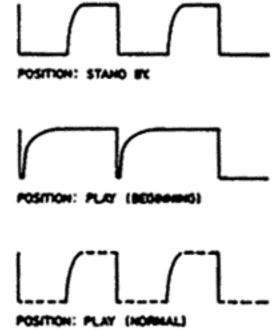
The repetition time of the MC signals is 11.3 μ sec.

- Place a disc on the turntable.
- In position PLAY or SERVICE POSITION 3, the MC signal corresponds to the figure below.

Note:

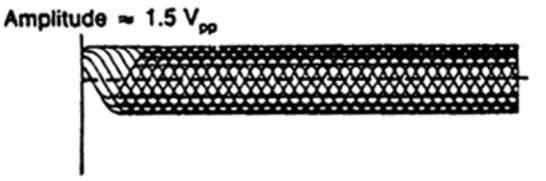
During start-up the duty cycle is 98%, then the duty cycle of the signal becomes about 50%.

See also Service Manual CDM-1: "Check of the motor control".



- Check the HF signal on test point (s) (eye pattern)
- Place a disc on the turntable.
- The HF signal should be present and be stable in the PLAY mode and in: SERVICING POSITION 3 after the run-in track has been read.
- In SERVICING POSITION 2 and during reading of the lead-in track the HF signal is not stable.

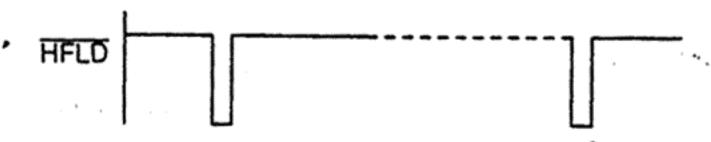
Position of oscilloscope 0.5 µs/DIV.



• Check the HFLD signal on test point 6

- Place a disc on the turntable.
- In the PLAY mode and in SERVICING POSITION 3 the HFLD signal is "high"; however, minor pulses may be present and in cause of disorders on the disc.
- In SERVICING POSITION 2 and during playback of track no. 15 of test disc 5A HFLD pulses are visible.

Position of the oscilloscope 5 ms/DIV



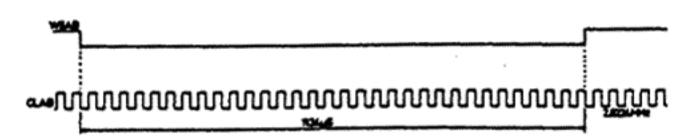
Check if the MUTE signal (pin 11; test point 6)
is "high"

When Filter-B IC is applied, the MUTE input will not be used.

- Check the CEFM signal (pin 27; test point 6)
- Place a disc on thr turntable.
- In stand-by mode (only the main s switch is depressed), the frequency lies between 2.82 MHz and 5.64 MHz.
- In the position PLAY and SERVICE POSITIONS 2 and 3, the frequency is 4.32 MHz.
- Check the Xin signal (pin 19; test point 69)
- The Xin frequency is 11.2896 MHz.
- If this frequency deviates, check test point 70;
 Xout signal, on Filter-B IC.
 This frequency should also be 11.2896 MHz.
- Check the timing signals meant for Filter-B IC
- Place a disc on the turntable.
- Select one of the following positions:
 SERVICE POSITION 2 or 3, or position PLAY.
- Trigger the oscilloscope with the WSAB signal (test point 4), pin 39).
- Check signals:

WSAB at test point (pin 39)
(Word Select from Decoder-A to Filter-B)
CLAB at test point (pin 38)
(Clock from Decoder-A to Filter-B)
and their interrelation.

There must be activity at test point (pin 37),
 DAAB signal (DATA from Decoder-A to Filter-B).

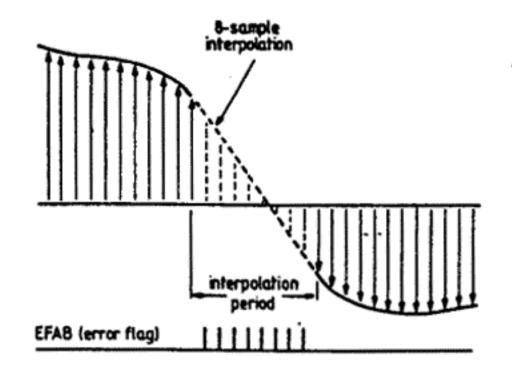


Check the EFAB signal (Error Flag from Decoder-A to Filter-B) at test point ◊> (pin 36)

- Place test disc 5A on the turntable.
- During playback, EFAB fulses should be present at test point for soft braking of the disc and during fast search (F.Forward, F.Reverse).

Note:

Filter-B IC is capable of interpolating linearly 8 successive EFAB pulses.



Check the Q-channel signals

- Place a disc on the turntable.
- Select one of the following positions:
 SERVICE POSITION 3 or position PLAY.
- Trigger on the QRA signal (Q-channel Request Acknowledge) test point (3); pin 30.
- Check signals QRA at test point (pin 30).

QCL at test point (pin 31). (Q-channel-clock)

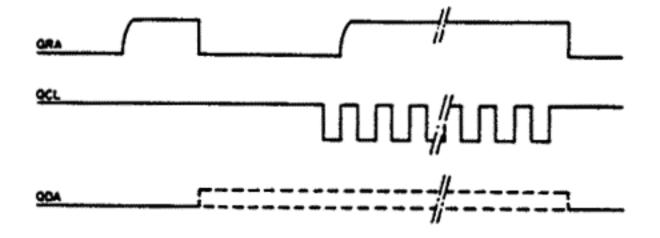
and their interrelation.

There should then be activity at test point (pin 29) QDA (Q-channel Data).

Note:

The QRA request is initiated by decoder μ P (QRA "high"). Then Decoder-A answers this request (QRA goes "low"). With the next leading clock pulse (QCL) the QRA signal is rendered "high" again by the decoder μ P.

As soon as the decoder μP has taken in enough information via QDA, QRA will go low again. That is why the QRA times vary each time.



Check the SSM signal (test point \$\sigma\$; pin 33) = Start-Stop turntable motor

Note:

After the motor start pulse, SWAB information (Subcoding Word clock) will become visible at this point. The period time of that signals is 136 μ sec.

Check the subcode clock signals

- Place a disc on the turntable.
- Select one of the following positions: SERVICE POSITION 3 or position PLAY.
- Trigger the oscilloscope with the SWAB signal at test point (a).
- Check the following signals:

SWAB at test point (3); pin 33

SCAB at test point (5), pin 35 (Subcode Clock from Decoder-A to Filter B)

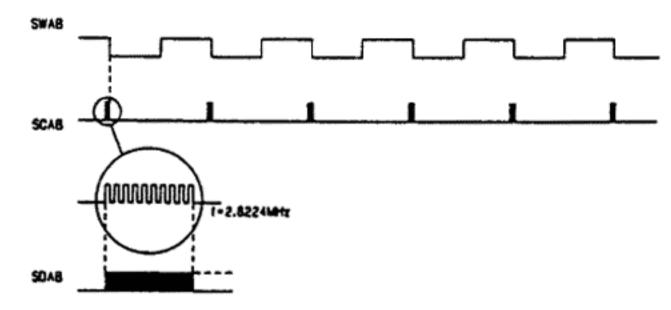
SDAB at test point (sp; pin 34 (Subcode Data from Decoder-A to Filter B)I

and their interrelations.

Note:

While the burst of 10 clock pulses, appear on SCAB the Q-channel information is transferred on SDAB. Hereafter the P-bit indication follows.

The P-bit "high" between two bursts of 10 clock pulses in case of pause indication and "low" in case of music indication.



Check the CRI signal

The CRI is "low" in case of track jumping. Player in position SEARCH.

Check the DEEM signal (test point ♠; pin 32)

- Place test disc 5 on the turntable.
- During playback of track no. 14 (recorded without PRE-EMPHASIS), the DEEM signal should be "low".
- During playback of track no. 15 (recorded with PRE-EMPHASIS), the DEEM signal should be "high".

II FILTER-B IC

Check the signals between Decoder-A IC and Filter-B IC

See sub. "I Decoder-A IC".

- Check the X IN signal (test points (s) and (b))

Check the timing signals meant for Filter B
 (WSAB, CLAB, DAAB signals; test points ♠, ♠
 and ♠).

Check the EFAB signal (test point 4)

- Check the subcode clock signals (SWAB, SCAB, SDAB signals; test points (3), (3) and (4).

Check the timing signals between Filter-B IC and DAC IC

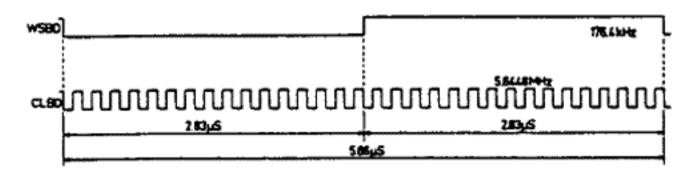
- Place disc on the turntable.
- Select one of the following positions:
 SERVICE POSITION 3 or position PLAY.
- Trigger the oscilloscope with the WSBD signal (Word Select from Filter B to DAC) test point (pin 18).

Check the following signals:

WSBD at test point (s); pin 18

CLBD at test point (clock signal from Filter B to DAC) and their interrelation.

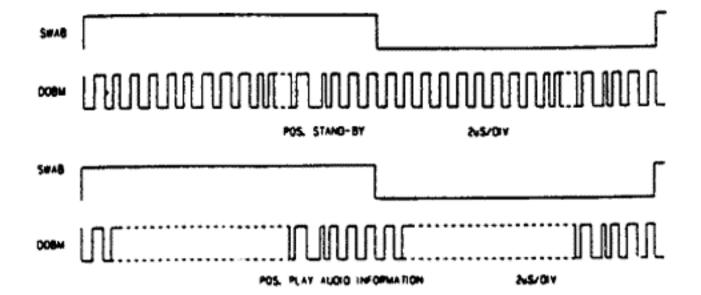
If an Audio disc is used, there should be activity at test point (pin 15) DABD signal (DATA from Filter B to DAC). If a disc with Digital Data (CD-ROM) is used, this point is continuously switched "low" by transistor Q537. In that case the word "data" appears on the display.



Check the DOBM signal (Digital Output)

- Place a disc on the turntable.
- Select the stand-by mode (only mains switch depressed).
- Trigger the oscilloscope with the SWAB signal (test point (3)).
- Check the DOBM signal (test point 49; pin 14). An empty audio signal has a fixed pattern. See drawing, "Stand-by".
- Select the PLAY mode.

Check the DOBM signal. See drawing "PLAY".



- In position SEARCH the ATSB signal is "low" test point (a); pin 22 (Attenuation Audio Signal)
- When the "µP panel" is applied, (a sub-printed circuit board) that houses IC Q271, test point (s) is not connected.

This signal is "low" in positions:

PAUSE

NEXT or PREVIOUS when jumping form one track to another.

Fast SEARCH when the Search button is kept depressed for some time.

III DAC IC (Dual Digital Analog Converter)

Check the signals between Filter-B IC and DAC IC

See sub. "Il Filter-B IC":

 Check the timing signals between Filter-B IC and DAC IC.

Check the output of the OP-AMP after the DAC IC

- Place a disc on the turntable.
- In position PLAY or in SERVICE POSITION 3, the analog (music) signal should be present at the output of the OP-AMP, after the lead-in track has been read.

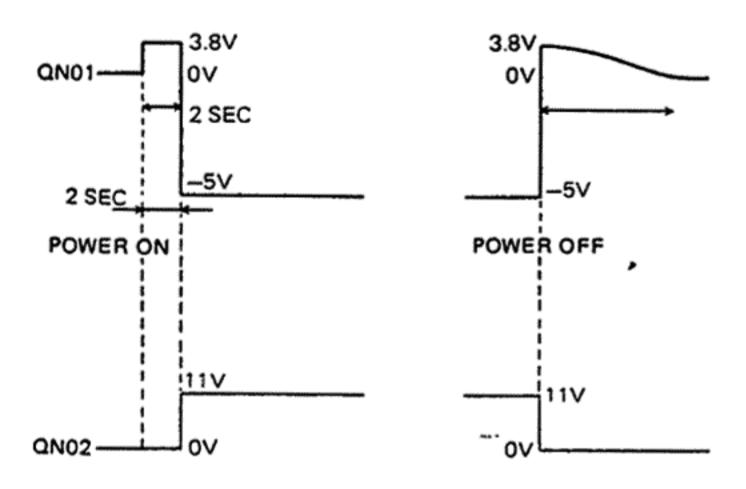
IV DEEM CIRCUIT

Check DEEM circuit

- Place test disc 5 on the turntable.
- During playback of track no. 14 (recorded without PRE-EMPHASIS) the DEEM signal at test point should be "low".
- During playback of track no. 15 (recorded with PRE-EMPHASIS), the DEEM signal at test point should be "high".
- During playback of track no. 14 the analogue signal should be present at the source of R564 (test point (2)).
- During playback of track no. 15 the analog signal at the source of R564 (test point (a) and R565 (test point (a)) should be 0 V...

V KILL CIRCUITL

 During switching on and off the mains voltage the signal on the collector of QN01 and QN02 should be as indicated in the figure below.



VI FAVOURITE TRACK SELECT (FTS)

Attention:

When repairing a CD player it is important that the cxontents of the FTS memory (EEPROM) should not unnecessarily be damaged.

If no complaints are reported about the functioning of the FTS, a check of the functions of the EEPROM should be left undone.

The EEPROM IC is in the Stand-by mode when CE and RDY are both high.

Selftest of the FTS μP

During the self-test of the FTS μ P, I/O Gate will not be tested.

Therefore this self-test can be executed without damage to the memory as indicated in General Test Points.

Annex I: LASER IS GIVING NO OR INSUFFICIENT LIGHT

Together with laser supply and the monitor diode the laser forms a feedback system.

A defect in the laser supply might thus result in destruction of the laser. Replacement of th laser (=new light pin) will not solve anything. The new laser will also be destroyed since the original fault in the laser supply is still present.

On the other hand it is impossible to check and repair a feedback system when one link is missing.

For this reason the so-called laser simulator 3 is supplied. Code number 4822 395 30229.

This laser simulator consists of a PCB which contains the laser and monitor simulation, a switch to test the On/Off position and a number of sockets. This PCB can be connected to the laser supply instead of the light pin so that the feedback system is closed.

Repair procedure:

Since the light pin is very sensitive to static charges, care should be taken that during measurements and adjustments of the laser power supply the potential of the aids and yourself equal the potential of the CD mechanism.

Detach light pin an connect laser simulator as follows: (connections on pre-amp PCB).

Take the flex PCB out of socket 11 and connect the simulator PCB with the socket.

Remove plug 16 and insert it in the socket on the simulator PCB.

Connect the plug with 4 wires to socket 16. Take out plug 17 and insert the plug with 1 wire in socket 17.

- Switch on the mains switch and ensure that the drawer is closed or else that the tray-end-in switch on the tray PCB (S004) is depressed. Now press the play key and check if the L-line of the servo µP, pin 21-2 on the pre-amplifier PCB, goes "low".
- In rest position the current through the laser diode should be ≤ 1 mA. For NEG. VOLT. lasers this can be checked as follows: Set the switch on the simulator PCB in the OFF position and the mains switch in the ON position.

Turn trimming resistor 3180 counterclockwise (min. R) and measure the voltage across resistor 3194 on the pre-amp. PCB.

On pre-amplifier PCBs with discrete components turn resistor 3180 clockwise (min. R) and measure the voltage across resistor 3194.

The voltage should be \leq 15 V.

Check of laser supply control

Set the switch on the simulator PCB in the ON position and measure the voltages between points +V and=V on the simulator PCB.

Resistor 3180 clockwise (max. R): $U_{+v-v}=225 \text{ mV} \pm 45 \text{ mV}$. On pre-amplifier PCBs with discrete components resistor 3180 counterclockwise (max. R): $U_{+v-v}=225 \text{ mV} \pm 45 \text{ mV}$.

R3180 counterclockwise (min. R): $U_{+v-v}=750 \text{ mV} \pm 150 \text{ mV}$.

On preamplifier PCBs with discrete components resistor 3180 clockwise (min. R): $U_{+v-v}=750 \text{ mV} \pm 150 \text{ mV}$.

Set resistor 3180 in the mid-position.

This is a preliminary adjustment. After the simulator PCB has been removed the laser current must be adjusted.

Fine adjustment of laser current

 Playback track 1 of test disc 4822 397 30096 (Disc without defects). Connect a DC voltmeter across resistor 3308 on the SERVO PCB circuit diagram D. Adjust the laser power supply with resistor 3308 is 575 mV \pm 50 mV.

Annex II: CHECKING d-FACTOR (Test points on servo PCB)

 Switch off AGC circuit (k-multiplier) and switch off offset circuit (d-multiplier). See sub G and H.

Place disc on turntable and set player in service loop 2.

- Check points (2) and (2).
 Value should be 0.7 V_{pp}.
 Frequency variation strongly depends on the eccentricity of the disc.
- Check points (2).
 Value should be 250 mV_{pp}.
- Check point (3).
 Value should be 200 mV_{pp}.
- Check point (3).
 Value should be 2 V_{pp}.
- Check points (3) and (38).
 Value should be 10 V_{pp}.
 The signals is more sine-shaped now due to filtering out of 650 Hz.
- Point (3) is hard to measure since switch is in position Yoc and thus connected with input of op-amp Q302 (pin 9).

However, a signal of 200 mVpp is present.

Check point 49.
 Value should be 9 V_{pp}.

Bring the player in service loop 3. With a disc on turntable and the AGC and offset-circuits are still switched off.

- Check point
 .
- Check point (a) on beam A of oscilloscope and check point (a) on beam B of oscilloscope while oscilloscope is triggered with point (a).
- Switch on the AGC-circuit and offset circuit.

Annex III: CHECKING k-FACTOR

(Test points on Servo PCB)

a. Static

Switch power on without depressing the Play button. I.e. RC0=high; RC0=low so switch Ya is in position 0 and switch Yc is in position 0.

- Check point (4)s.
 Value should be 9 V_{pp}.
- Check point 49.
- On point (29) now appears a sine-wave signal of 650 Hz, 300 mV, and 180-45=360°shifted in phase relative to signal on point (49).
- Check point 47.
 Value should be 1.5 Vpp.
- Check point 48.
 Value should be 1 Vpp.
- Check points (9), (5), (5) and (4) relative to each other.
 - Amplitudes are 5V.
- Check integrator IC Q303 (4/4)

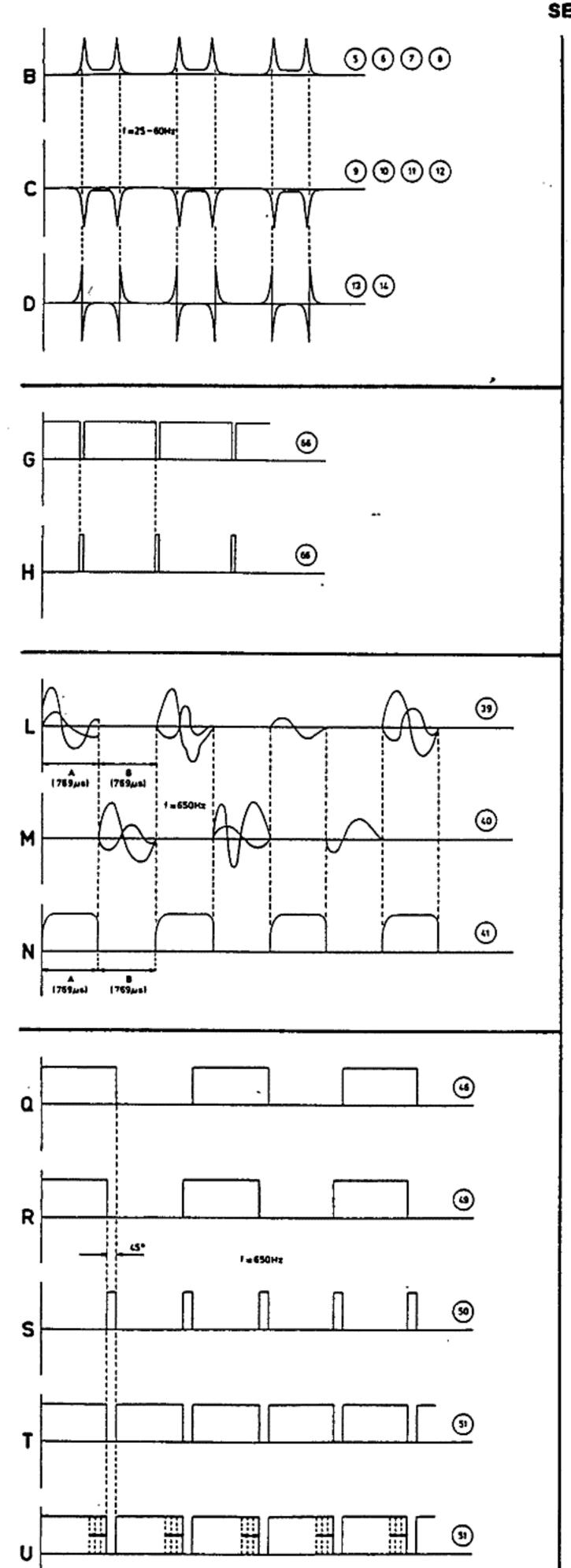
b. Dynamic

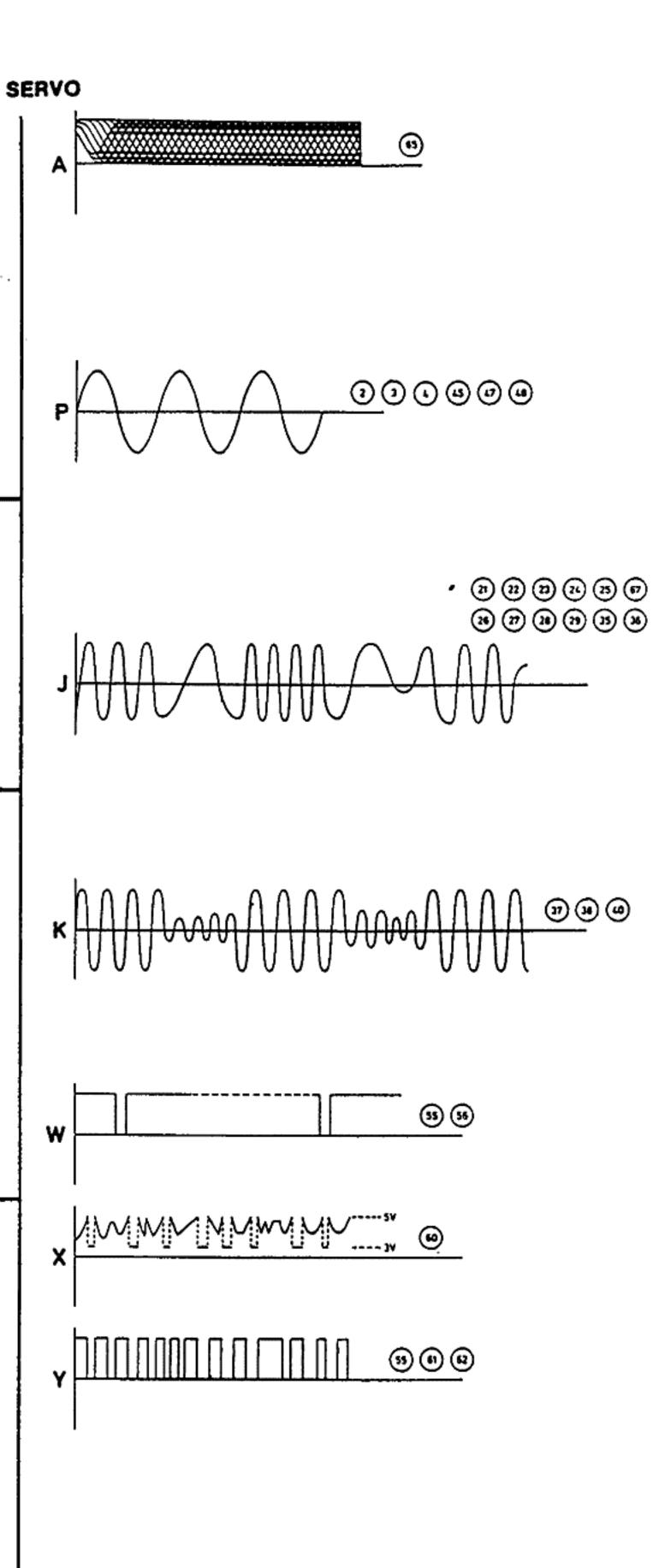
Insert disc, select service loop 2 and check if the signal on point (2) equals to 7 Vpp.

Select service loop 3.
 Now RC0=high and RC0=low.
 So switch Y₂ is in position 1.
 Switch Y₂ switches at f=650 Hz.
 Point ⑤ is low; so point ⑥ is in phase point ⑥.
 Now fig. U should be present on point ⑥ with duly cycle jittering round 50%.

Annex IV: CHECKING RF PRE-AMPLIFIER (measure points on pre-amp. PCB)

- a. Check DC-voltages on transistor 6103, 6104, 6105, 6109, 6110, 6111.
- For checking sensitivity, frequency and delay characteristic, proceed as follows:
 - Take flex PCBs of sockets 10 and 11.
 - Take plugs 18, 17, 12, 13, 14 and 15 out of sockets.





SERVO

Nr.	See	Position	Amplitude	1	Time base
1 2 3 4 5	PPPB	see fault finding meth.	0,6 Vp-p 6 Vp-p 5 Vp-p 40-80 mV	10 Hz 10 Hz 10 Hz 25-60 Hz	
6 7 8 9 10	8 8 8 C C	see fault finding meth.	40-80 mV 40-80 mV 40-80 mV —2 V —2 V	25-60 Hz 25-60 Hz 25-60 Hz 25-60 Hz 25-60 Hz	
11 12 13 14	0000	see fault finding meth. see fault finding meth. see fault finding meth. see fault finding meth.	-2 V -2 V -8 V, +8 V depends on R3158	25-60 Hz 25-60 Hz 25-60 Hz 25-60 Hz	*.
15		see fault finding meth.			•
20 21 22 23 24 25 26	1 1 1	see fault finding meth.	12-14 Vp-p 0,7 Vp-p 0,7 Vp-P 0,2 Vp-p 0,25 Vp-p 20 mVp-p		
27 28 29 29 30 31	J J P	see fault finding meth. see fault finding meth. see fault finding meth. ON see fault finding meth. see fault finding meth. see fault finding meth.	800 mVp-p 800 mVp-p 6 Vp-p 0,3 Vp-p		
32 33		see fault finding meth. see fault finding meth.			
35 36 37 38 39 40	J K K L	see fault finding meth.	200 mVp-p 2 Vp-p 10 Vp-p 10 Vp-p 0-4 Vp-p 9 Vp-p		A = 769 μs B = 769 μs A = 769 μs B = 769 μs
40 41	N	see fault finding meth. see fault finding meth.	0-4 Vp-p 6 Vp-p		$A = 769 \mu s$ $B = 769 \mu s$ $A = 769 \mu s$ $B = 769 \mu s$
45 46 47 48 49	PQPPR	ON ON ON ON	9 Vp-p 0-5 V 1,5 Vp-p 1 Vp-p 0-5 V	650 Hz 650 Hz 650 Hz 650 Hz 650 Hz	A = 769 μs B = 769 μs
50 51 51 52 55	S T U	ON ON service loop B see fault finding meth. service loop A	0-5 V 5-0 V 5 V	650 Hz 650 Hz 650 Hz	
55 56 57 60 61	W W X	play (with test disc) play (with test disc) see fault finding meth. service loop A	5-0 V 5-0 V 5-3 V		
62	Y	service loop A service loop A	5-0 V 5-0 V		
65	A	play	1 Vp-p		
66	G	see fault finding meth.	5-0 V		
, 66 67	1 H	see fault finding meth. see fault finding meth.	0-5 V		

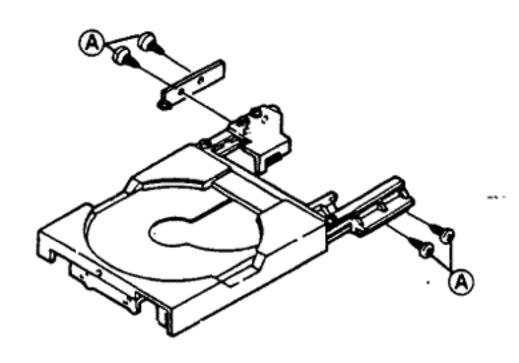
BLOCK DIAGRAM WARDS INFOMATION

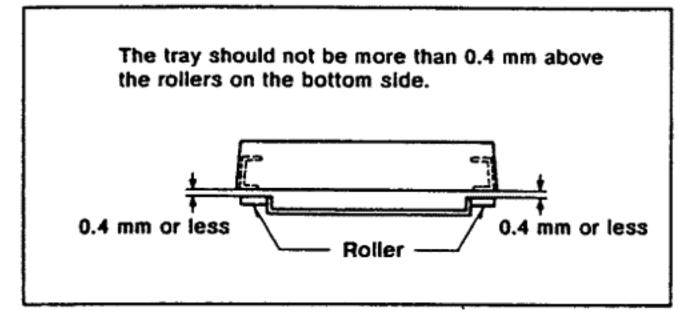
DACO - DAC3	Control bit for radial circuit	SSM	Motor Start-Stop signal
DAC	Cirrent output for track jumping	MUTE	Mute signal
DO	Drop out detector signal	MUSB	Soft Mute signal
D1 - 4	Photodiode Currents	PD/OC	Phase detector-oscillator control
FE	Focus error signal	QCL	Q-channel Clock signal
HF	HF output for DEMOD	QDA	Q-channel Data signal
HFLD	HF detector output for DEMOD	QRA	Q-channel Request Aknowledge
MSC	Motor control signal	SCAB	Subcode clock Decoder-A to Filtor-B
RE	Radial error signal (Amplified RE2 -	SDAB	Subcode data Decoder-A to Filter-B
	RE1 currents)	SWAB/SSM	Subcode Word/Start-Stop Motor signal
RE1	Radial error signal 1 (Summation of	WSAB	Word select Decoder-A to Filter-B
	amplified currents D3 and D4)	WSBD	Word select Filter-B to DAC
RE2	Radial error signal 2 (Summation of amplified currents D1 and D2)	XIN	Oscillator signal in Decoder-A
TL/INT	Track loss signal	XSYS	Oscillator signal OUT Filter-B
Vc	Control voltage for turntable motor	RDIR	Radial current switch control signal Nomal, or Revers
ATSB	Attenuation of Audio level in search position (cueing)	RP	Radial puls after Track Jump
CEFM	Clock 4.3218 MHz	FN	Focus Neutral
CLAB	Clock signal Decoder-A to Filter-B	ANIN	
CLBD	Clock signal Filter-B to DAC	HFLS	HF Loss signal
CRI	Counter Reset Inhibit	SRDO	Signal Radial ON/OFF for Track jump
DAAB	Data signal Decoder-A to Filter-B	RCO	Switch Digital to Analogue
DABD	Data signal Filter-B to DAC	FC1, FC2	Focus UP/DOWN signal
DEEM	Deemphasis ON-OFF signal	FCO	Focus ON/OFF signal
DOBM	Digital out signal	L	Laser ON/OFF signal
EFAB	Error flag Decoder-A to Filter-B	BUSY	μ-COM Communication Clock
IREF	Reference current	RXD	μ-COM Communication Recive Data
INCF	Hererence carrein	TXD	μ -COM Communication Telex Data

Loading Tray Mechanism

Cautions When Servicing

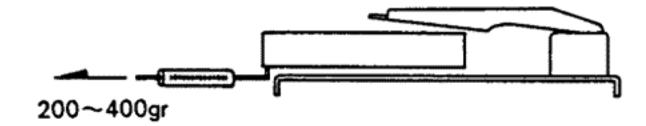
- Installation of Tray and Tray Case
 (Upon replacement of the tray case due to breakage, etc.)
- If the position with respect to the tray's front panel window is incorrect, lossen screws (A) and move the tray within the range of play of the hole to adjust. For the inclination of the tray, refer to diagram below.



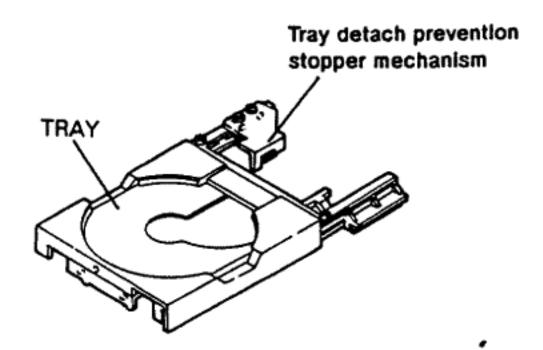


Adjust the inclination as well with screws (A).

2 The tray's working force should be set to between 200 and 400 gr (when power is off).



2. If Tray has become detached downward

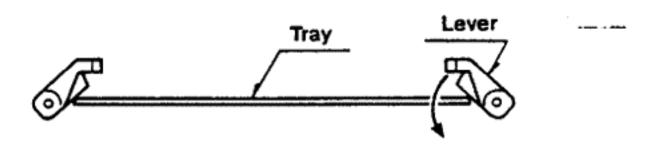


Take care in the following instances as the tray will become detached downward.

- The tray will become detaced if pressed downward with the stopper mechanism removed while the drawer is open.
- The tray will become detaced if pressed downward when there is no subchassis (CDM-1).
 (The same is true when the tray is closed with no subchassis.)

Use the following procedure to reinstall.

Lower the lever and place the tray on the projection.



2 Next, with the tray pressed down, lower the other lever and place the tray on its projectin.



NOTE:

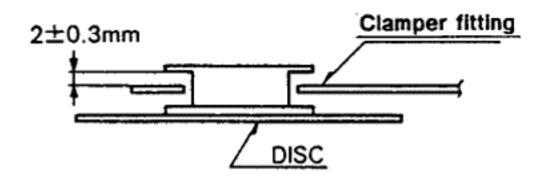
Be sure to lower only one lever at a time as the tray cannot be lifted if they are both lowered.

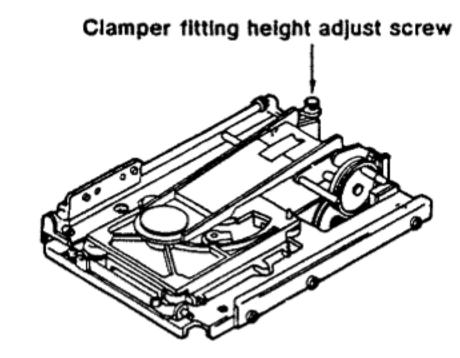
NOTE:

If the tray is forced back to its original position, the two pins in the tray case may bend.

3. If Subchassis (CDM-1) has been replaced

The height of the subchassis turntable differs from one unit to the next, so it is necessary to adjust according to the height of the turntable so that the magnet clamper is not in contact with the clamper fitting. (Standard 2±0.3 mm)



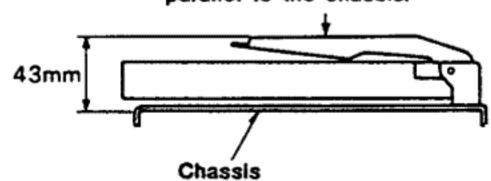


When the height of the clamper fitting is adjusted, the position when the clamper is up must be readjusted. Use the following procedure.

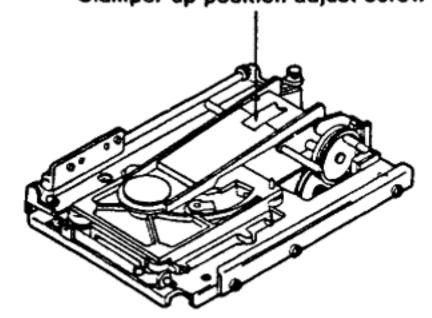
Disc clamper position

When up Max. 43 mm
(Tray and clamper should not come into contact when try is opened and closed.)

To the eye, this fitting appears parallel to the chassis.

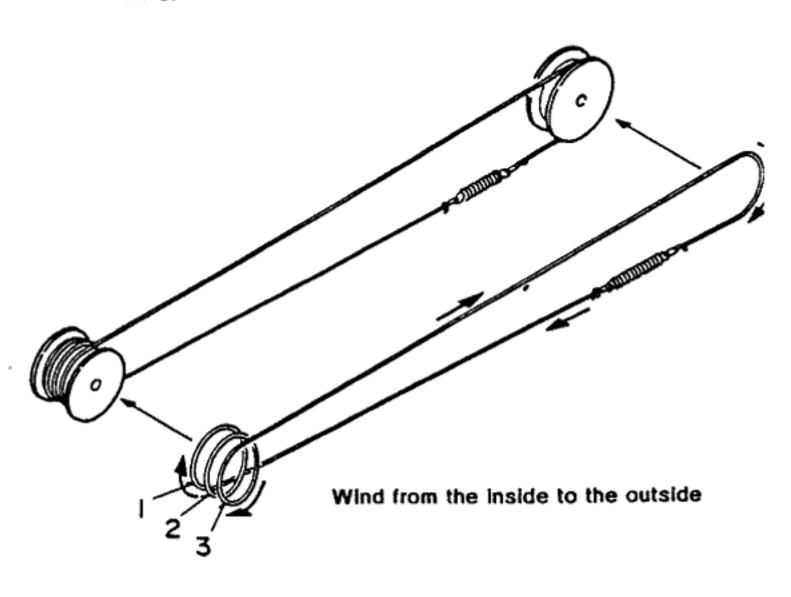


Clamper up position adjust screw

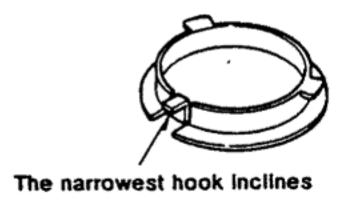


4. Others

1 Refer to the diagram below to install the loading wire.



- 2 All switches on the mechanism are of the socket type. If a switch breaks, remove the socket to replace.
- 3 Use to the structure of the hooks of the magnet clamper (094M), incline as indicated below to remove and install the magnet clamper when replacing it.



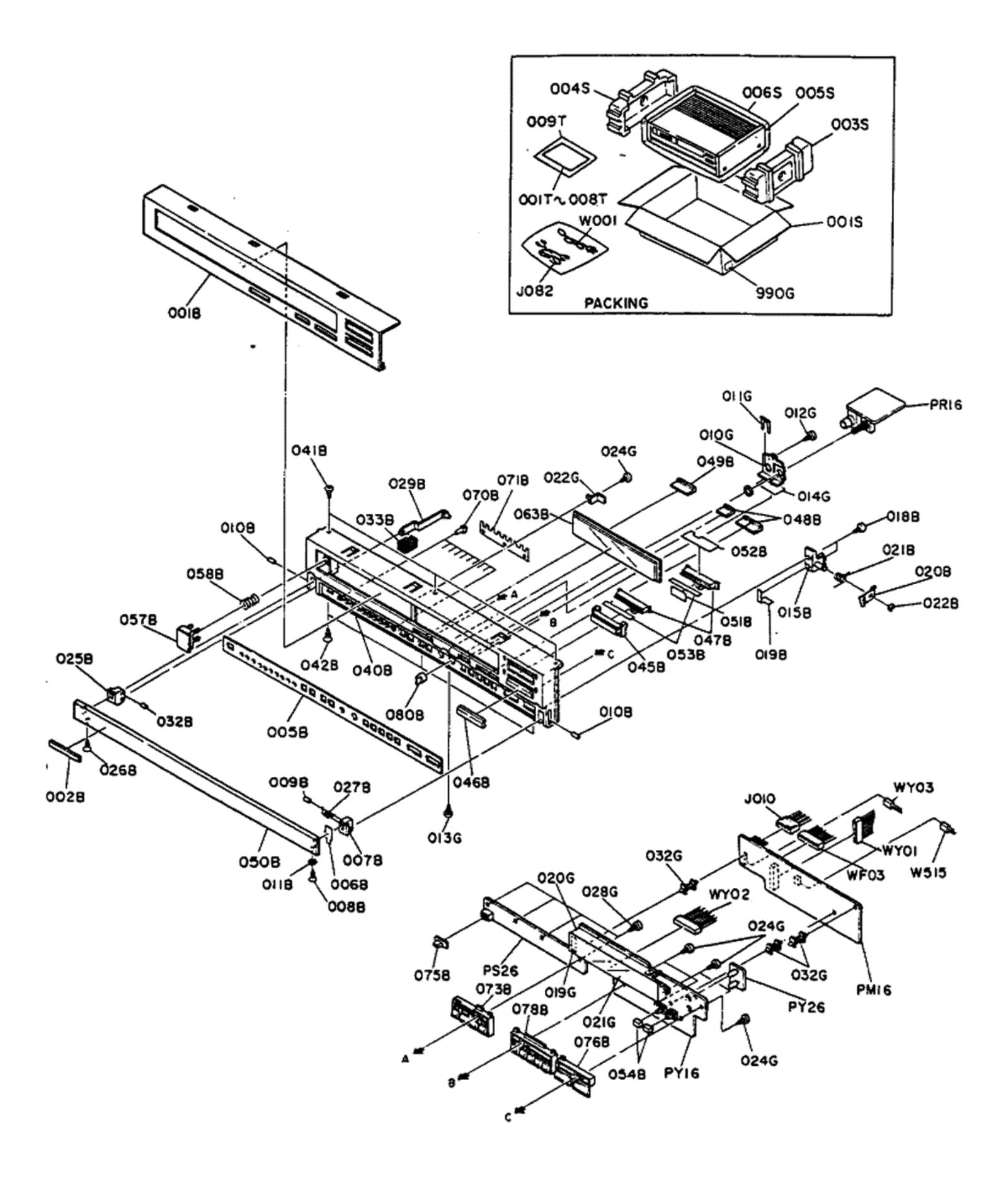
TECHNICAL SPECIFICATIONS

Audio Characteristics
Number of channels
Frequency response
Digital to analogue convarsion
Dynamic range Better than 96 dB
Signal-to-noise ratio
Channel separation
Total harmonic distortion
Wow & flutter
Error correction system
Audio output level
Optical Data Read System
Laser
Wave length
Signal Format
Sampling frequency
Quantization
Power Supply Section
Power requirements
Power consumption
Fuse capacitance
Cabinet and Others
Dimensions (W x H x D)
Weight
Allowable operating temperature
Allowable operating humidity
Provided Accessories
Remote control unit (RMC-94)
Dimensions (W x D x H)
Weight (without batteries) 100 g Battery (AA/R06) 2 Audio connection (RCA pin-jack) cord 1 pair
Audia connection (RCA pin-iack) cord
Addio connection (Non pin-jack) cord
Compact Discs
Diameter of disc
Thickness
Rotating direction
Scanning velocity
Revolution (spindle) speed
Playing time (theoretical)
Track pitch

^{*} Improvement may result in changes in specifications and design without notice.

EXPLODED VIEW AND PARTS LIST

[C01-99] FRONT PANEL AND PACKING MATERIALS



REF. DESIG.	PART NO.	DESCRIPTION	RE DESI
			\dashv
0018	157K248010	Front Panel	JO1
002B	274H251020	Badge	W5
0058	157K063020	Escutcheon, Front Panel	WF
006B	157K265030	Indicator	WY
007B	157K153010	Hinge (R) F.H. Taptite Screw F2.6 x 8	WY
0088 0098	51502608U0 157K112010	F.H. Taptite Screw F2.6 x 8 Shaft, Lock	w
0108	157K112030	Shaft, Hinge	
0118	54050200R0	T.L. Washer	001
0158	157K 160500	Bracket (K), Lock	
			002
0188	51280308M0	8.H. Tapped Screw B3 x 8	003
0198 0208	157K123010	Contactor Hook, Lock	004
0218	157K115010	Spring	005
022B	64002500R0	RG Ring, E Type #2.5	006
0258	157K153020	Hinge (L)	007
0268	5150260880	F.H. Taptite Screw F2.6 x 8	800
0278	157K115020	Spring, Open	009
029B	157K125500	Joint (K), Dumper	
032B	157K112050	Shaft	001
0338	203C056010	Buffer	003
0408	157K 105010	Chassis, Front	005
0418	51500308M0	F.H. Taptite Screw F3 x 8	006
0428	51500308M0	F.H. Taptite Screw F3 x 8	
0458	157K270060	Button, Play/Replay	108:
046B	157K270090	Button, Pause/Stop	1
047B	157K355010	Lens	awoo
048B 049B	157K270040 157K270070	Button, FTS/Track Button, Open/Close	
0508	157K063010	Escutcheon, Door	990
0300	13711000010		
0518	157K056010	8uffer	
0528	157K 109010	Shield	
053B	157K 107010	Sheet	
0548	416C056050	Buffer Buses Pause	11
057B 058B	157K270050 157K115030	Button, Power Spring, Power Button	
063B	157K158010	Window	
070B	157K270080	Button	11
071B	157K116010	Leaf Spring	11
0738	157K270030	Button, Select/Cancel	11
		Vach Times	1 1
0758	157K154010 157K270010	Knob, Timer Button, REV-FF/Index	
076B 078B	157K270020	Button, LAP/AMS	
080B	135K154110	Knob, Level	11
			1
010G	157K160010	Bracket, Phone Jack	
011G	198T114010	Stopper	
012G	51280308M0	B.H. Tapped Screw 83 x 8 F.H. Taptite Screw F3 x 8	1 1
013G 014G	51500308M0 157K123020	F.H. Taptite Screw F3 x 8 Contactor	
014G	2818056040	Buffer	1 1
020G	157K271010	Holder, FL	
021G	157K303010	Mask, FL	11
022G	157K104030	Retainer, Display P.W. Board	11
024G	51280308M0	8.H. Tapped Screw 83 x 8	1 1
0000	213H118010	Spacer	
025G 028G	5128030880	B.H. Tapped Screw B3 x 8] [·
028G	157K118010	Spacer	1 1
33.0			11
i			
			1 1
l	ł	1	1 1

REF. DESIG.	PART NO.	DESCRIPTION
J010	YJ06001050	Jack, 5P
W515	YB00390120	Connective Cord, 3P
WF03	YB00700250	Connective Cord, 14P
WYOI	YB00180330	Connective Cord, 13P
WY02	YB00230290	Connective Cord, 13P
WY03	YB00130360	Connective Cord, 5P
		PACKING
001T	157K851310	User Manual (N, A, W)
	157K851110	User Manual [F]
002T	157K851320	User Manual, Spec (N, A, W)
003T	157K856010	Circuit Diagram (N, W)
004T 005T	158K861020 9631000090	Label, FTS (F) Warranty Card (A)
1 0051	157K813500	Envelope (F)
006Т	157K854010	Warranty Card [F]
007T	9611000050	User's Card (F)
008T	9540000010	License
T600	9012540010	Polyethylene Bag
0015	157K801010	Packing Case
0038	157K809010	Cushion (A)
0045	157K809020	Cushion (L)
005S	175H107010	Sheet
006S	9091111030	Polyethylene Sheet
J082	ZD01000230	Connective Cord, Audio
&W001	ZC01805010 ZC02006020	A.C. Power Cord (N, W)
		A.C. Power Cord [A]
990G	9510901180 9510911100	Label (A, F) Label (N)

REF. DESIG.	PART NO.	DESCRIPTION		REF. DESIG.	PART NO.	DESCRIPTION
0288	1207276010	Piston, Dumper	İ	001L	158K267010	Heatsink
0358	157K160030	Bracket, Dumper	Ì	003L	51280308W0	B.H. Tapped Screw B3 x 8
036B	51280308M0	B.H. Tapped Screw B3 x	8			
0598	157K063030	Escutcheon, Drawer		A001	167K304510	Mechanism (K)
0608	157K104010	Retainer, Drawer		1		
0618	51280308M0	8.H. Tapped Screw B3 x	(8	△F001	FS10020800	Fuse T200mA (N, A, W)
Q62B	157K251010	8adge .	1	.	FS10050610	Fuse 0.5A [F]
0658	158K053010	Cover	.			1-1-5
066B	51280308M0	B.H. Tapped Screw B3 x	. 8	∆ J001	YJ08000290 YJ08000300	Jack, Fuse Holder (N, A, W) Jack, Fuse Holder (F)
0010	157K257010	Lid, Top Cover (Front)	- 1	J011	YJ06001070	Jack, 9P
002D	157K257020	Lid, Top Cover (Rear)	.	∆ J091	BY05030040	Voltage Selector (N, A, W)
003D	51280308M0	8.H. Tapped Screw B3 x		₹ 1003	YP04000580 YJ15000010	Plug, AC Inlet (N, A, W) Jack
004D	51280308M0	B.H. Tapped Screw B3 x	'*	JD03	1313000010	Jack
0050	158K056010	Buffer Bassians Ton Cours		A L001	TS16810010	Power Transformer (N, A, W)
006D	157K104020	Retainer, Top Cover 8.H. Tapped Screw B3 x		a 200.	TS16810020	Power Transformer (F)
007D	51280308M0	8.H. Tapped Screw B3 x Side Panel (L)	, ,	1	1510010020	· Over · · onzionna (· ·)
011D	157K249010 3906259010		1	∆ W001	YC01800390	A.C. Power Cord [F]
012D		Bushing B.H. Tapped Screw B4 x	30	۵,1100.	1.00.00000	7.0.7 0000 (1)
013D	51280430U0	D.m. rapped ocrew B4 x		W201	Y8000820250	Connective Cord, 15P
0140	157K249020	Side Panel (R)	i	W202		Connective Cord,
014D	3906259010	Bushing	i	W203	YB00450190	Connective Cord, 14P
015D		_	30	111200	, 500,00,00	
016D	51280430U0	B.H. Tapped Screw B4 x		W501	YB00430040	Connective Cord, 2P
001G	158K105010	Chassis, Main		W510	YB00230300	Connective Cord, 4P
001G	158K121010	Link, Power Switch	1	W511	YB00500420	Connective Cord, 3P
005G	158K160050	Bracket, Power Switch	- 1	W515	YB00390120	Connective Cord, 3P
006G	51280308M0	B.H. Tapped Screw B3 x	. 8	W516	YB00060240	Connective Cord, 8P
007G	51100306M0	B.H.M. Screw 83 x		W803	YB00060240	Connective Cord, 9P
026G	51280308M0	B.H. Tapped Screw B3 x		1		•
027G	51280308M0	B.H. Tapped Screw B3 x		1		
029G	4214118010	Spacer		1		
035G	158K104040	Retainer, Front	1	1		
036G	51280308M0	B.H. Tapped Screw B3 x	8	1		
			- 1		l i	
037G	51280308M0	B.H. Tapped Screw B3 x	8	1		
051G	51500308M0	F.H. Taptite Screw F3 x	8	1		
055G	158K257020	Lid, Bottom Cover	.	1		
056G	51280308M0	B.H. Tapped Screw 83 x	8	1	1 1	
060G	176H057020	Leg	. 1	1		
061G	51280308M0	B.H. Tapped Screw B3 x				
065G	51280308M0	B.H. Tapped Screw B3 x	**	1		
066G	157K112060	Shaft, Transport				
069G	51260408M0	B.T. Screw B4 x		1		
070G	158K067010	Cap, Transport Shaft				
075G	51280308M0	B.H. Tapped Screw B3 x	8	1		
901G	157K250010	Rear Panel (N, A, W)	ļ	1		
	157K250020	Rear Panel (F)		1		
902G	51280308M0	B.H. Tapped Screw B3 x				
905G	51280308M0	B.H. Tapped Screw B3 x				
906G	51280308M0		[W,A,W]	, i		
908G	54050300R0	T.L. Washer	I			
910G	1455259120	Bushing, AC Power Cord (F)	1			
990G	9510901180 9510911100	Label (A, F) Label (N)				
0010	2911861110	Label, Caution (N, A, W)				
991G	187H265010	Indicator, Made in Japan (N, A	⊾wı I			
992G 993G	105K861070	Label, Laser (N, A, W)	7,771			
9930	101K861030	Label, Laser [F]	l			
995G	158K861010	Label, Transport				
2530	.50.001010	acces, transport	I			
			ŀ			

125M 167K105030	REF. DESIG.	PART NO.	DESCRIPTION	N	REF. DESIG.	PART NO.	DESCRIPTIO	ON
127M	!			:				
167K-051010	002M	167K105030	Chassis, Main	1	125M	167K271500	Holder (K), Slide Bearing	1
1014M 152003080	4				1		B.H. Tapped Screw	
1014M 51280308B0 B.H. Tapped Screw B3 x 8 135M 197K-27101 51280308M0 B.H. Tapped Screw B3 x 8 135M 140M 147K-160150 B.H. Tapped Screw B3 x 8 136M 140M 147K-160150 B.H. Tapped Screw B3 x 8 136M 140M 147K-160150 B.H. Tapped Screw B3 x 8 136M 140M 147K-160150 B.H. Tapped Screw B3 x 8 136M 140M 147K-160150 B.H. Tapped Screw B3 x 8 136M 140M 147K-160150 B.H. Tapped Screw B2 x 8 140M 157K-160150 B.H. Tapped Screw B2 x 8 140M 157K-160150 B.H. Screw B2 x 8 157M				83 x 8	1			50 0
135M 137K282010 Pulley, Wire Wheel 136M 137K18010 137K18010 137K280200 137K18010 137K18010 137K18010 137K18010 137K18010 137K280200 137K18010 137K18010 137K280200 137K18010				23 v 8				F3 x 6
1016M 54002500R0 RG Ring, E Type 42.5 HAM 167K16010 Bracket (I.), Tray Bracke				3 ^ 0				83 x 8
1019M 167X262030 167X2620		1		2.5				55 % 5
0.22M 167K/2864010 0.25M 167K/15010 0.25M 167K/15010 0.25M 167K/15010 0.25M 167K/15010 0.25M 167K/16010 0.25M 167K/280200 0.25M					141M			
	1			2.5	1		-	
0.22M 51102604A0 518t, M.Screw 82.5 x 4 515M 167K190101 522M 167K264010 58t, Tray Drive 512M 167K259050 515M 167K054010 501K 517K195020 501K 517K195020 501K195020 501K1950200 501K1950200 501K1950200 501K1950200 501K1950200 501K1950200 501K1950200 501K1950200 501K195020 501K1950200	021M	167K262040	Pulley, Motor	1	143M	51282604U0	B.H. Tapped Screw	B2.6 × 4
D25M 167K:264010 Belt, Mrotor Selt, Tray Drive 155M 167K:269030 Bushing Selt, Tray Drive 155M 157K:064010 Spring Selt, Tray Drive 156M 51280308M0 Sh.H. Tapped Screw B2 x 8 Sh.H. Tapped Screw B2 x 8 Sh.H. Tapped Screw B3 x 8 Sh.H. Tapp		51102604A0	R H M Screw B	826 V 4	151M	167K101010	Support	
0.26M 167K/264010 28M 167K/264010 28	1			32.0 7 7				
D27M 167K125010 Joint, Wire Rope Spring			-	1				
O31M 51100208A0 B.H.M. Screw B2 x 8 160M 167K156500 B.H. Screw B2 x 14 161M 167K354500 B.H. Screw B3 x 8 160M 167K354510 Lever (I.), Tray Lift Sangle (I.) Lever (I.), Tray Lift Lever (I.), Tray Lift Sangle (I.) Lever (I.), Tray Lift Sangle (I.) Lever (I.), Tray Lift Lev			Joint, Wire Rope		•			B3 x 8
0.35M 157K.160190 0.40M 157K.160190 0.40M 157K.160190 0.40M 157K.160190 0.40M 157K.160190 0.44M 51280308M0 0.44M 517K.15030 0.44M 51280308M0 0.44M 517K.15030 0.44M 517K.05030 0.								*
0.35M 167K160190 Bracket (KI, Motor 0.40M 167K160500 Bracket (KI, Motor 0.40M 167K160500 Bracket (KI, Motor 0.40M 167K160500 B.H. Tapped Screw 8.3 x 8 167K156500 167K160500 B.H. Tapped Screw 8.3 x 8 167K259010 167K26020 0.49M 167K36020 0.49M 167K16030 0.49M 167K16030 0.49M 167K16030 0.49M 167K16030 0.49M 167K36020 0.49M								
0.40M 167K160510 51280308M0 3 H. Tapped Screw B3 x 8 165K 165M 167K 15050	1			32 × 14	1			
0.44M 51280308M0 S.H. Tapped Screw B3 x 8 165M 167K 163010 Tray, Disc University Disc Tray, Disc University								
				33 x 8	1			
0.46M								
OATM 167K262020 OABM 64002500R0 OABM 64002500R0 OABM CANDER OABM O	1						4. ,	
048M 64002500R0	Ł		- , , ,	2.5	1			
0.49M 167K282040 0.50M 511026040A 0.51M 167K284010 0.52M 1.52M 1	•					I		
050M 051M 051K264010 051M 167K264010 052M 167K264010 052M 167K264010 052M 167K264020 050M 167K264010 051M 051280038M0 051M 0514000108M0 051M 051280038M0 051M 0514000108M0 051280038M0 051M 051280038M0 051				2.5	1		,	
051M 167K254010 052M 167K254020 050M 167K160130 051M 167K254020 050M 167K160130 051M 052M	3			32.6 x 4		1		
052M 167K161030 Color				2.0				
061M 51280308M0 B.H. Tapped Screw B3 x 8	052M	167K264020	Belt, Cam Drive		190M			Guide
December						1		
063M 51100214A0 B.H.M. Screw B2 x 14 503M 167K112020 Shaft Sh	061M	51280308M0	B.H. Tapped Screw B	33 × 8	194M	64001200R0	RG Ring, E Type	φ1.2
063M 51100214A0 B.H.M. Screw B2 x 14 503M 167K112020 Shaft Sh	062M	51100208A0	R H M Screw B	22 × 8	501M	158K304500	Mechanism (CDM-1)	
167K 150110					1			
071M 51280308M0 072M 51100315A0 074M 075M 075M 075M 075M 075M 079M 0								
073M 167K115030 Spring, Down Adj. Spring, Down Adj. Shaft, Clamper Bracket Shaft, Clamper Bracket Shaft, Clamper Bracket Shaft, Tray Lever Shaft, Tray Lever Shaft, Tray Lever Lever (K), Clamper Drive Shaft, Tray Lever Lever (K), Clamper Drive Shaft, Tray Lever Lever (K), Clamper Drive Shaft, Tray Lever Shaft, Tray Lever Lever (K), Clamper Drive Shaft, Tray Lever Shaft, Tray Lever Shaft, Tray Lever Lever (K), Clamper Drive Shaft, Tray Lever Shaft, Tray L				33 x 8	505M			
074M 167K12060 64002500R0 64002500R0 167K12040 080M 167K112040 080M 167K15010 084M 167K15010 085M 167K16010 086M 167K354520 167K354250 167K35	1			33 x 15	1		•	
075M 64002500R0 079M 167K112040 167K112040 167K354520 Lever (K), Clamper Drive 511M 51282604U0 167K354520 Lever (K), Clamper Drive 513M 167K150250 B.H. Tapped Screw B2.6 x 4 Lever, Stopper B.H. Tapped Screw B2.6 x 4 Lever, Stopper B.H. Tapped Screw B2.6 x 4 Lever, Stopper S1282604U0				1				
167K112040 167K354520 Shaft, Tray Lever Lever (K), Clamper Drive S13M 51282604U0 167K354250 Spring, Pull Down Leaf Spring SH. Tapped Screw B2.6 x 4 Lever, Stopper S15M S157030480 Spring				2.5				P3 x 3
080M 167K354520 Lever (K), Clamper Drive 513M 167K354250 Lever, Stopper 083M 167K115010 Spring, Pull Down 513M 167K354250 Lever, Stopper 084M 167K116010 Leaf Spring 515M 5157030480 Spacer 085M 51282604U0 B.H. Tapped Screw B2.6 x 4 516M 4397115210 Spring 087M 167K354010 Buffer Lever, Clamper M002 MM01200130 D.C. Motor, Tray Drive 088M 51100310A0 Spring, Up Adj. M003 MM01200130 D.C. Motor, Tray Drive 090M 167K115030 Spring, Up Adj. M003 MM01200130 D.C. Motor, Tray Drive 091M 51280308M0 B.H. Tapped Screw B3 x 8 S001 SS01020590 Slide Switch, Tray Out 095M 167K305500 Magnet (K) S004 S00120590 Slide Switch, Clamper Down 103M 167K160530 Bracket (K), Tray Guide RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide	•							B2.6 x 4
167K116010 Leaf Spring S1282604U0 S1282604U0 S1282604U0 S1282604U0 S1085M S1282604U0 S1085M S1282604U0 S167K056030 S167K056030 S167K056030 S167K056030 S100310A0 S1280308M0 S1280308M0 S1280308M0 S167K056010 S167K05	080M	167K354520	Lever (K), Clamper Drive	1				
167K116010 Leaf Spring S1282604U0 S1282604U0 S1282604U0 S1282604U0 S1085M S1282604U0 S1085M S1282604U0 S167K056030 S167K056030 S167K056030 S167K056030 S100310A0 S1280308M0 S1280308M0 S1280308M0 S167K056010 S167K05	083M	167K115010	Socios Bull Dawn		51414	2027110050	•	
085M 51282604U0 B.H. Tapped Screw B2.6 x 4 516M 4397115210 Spring 086M 167K056030 Buffer Lever, Clamper M002 MM01200130 D.C. Motor, Tray Drive 088M 51100310A0 B.H.M. Screw B3 x 10 M003 MM01200130 D.C. Motor, Tray Drive 089M 167K271030 Spring, Up Adj. Holder S001 SS01020590 Slide Switch, Tray In 091M 51280308M0 B.H. Tapped Screw B3 x 8 S002 SS01020590 Slide Switch, Tray Out 095M 167K056010 Magnet (K) S004 SS01020590 Slide Switch, Clamper Down 103M 167K160530 Bracket (K), Tray Guide Roller, Tray Guide Roller, Tray Guide S006 SS01020590 Slide Switch, Laser Safety 108M 167K259020 Bushing, Front Guide B.H. Tapped Screw B3 x 8 S01020590 Slide Switch, Laser Safety 120M 167K056020 Buffer Bushing, Front Guide B3 x 8 S01020590 S01020590 S01020590 S01020590 S0102059				1				D2 v 4
086M 167K056030	,	1		32.6 x 4	4		•	F3 X 4
088M 51100310A0 B.H.M. Screw B3 x 10 089M 167K115030 Spring, Up Adj. 090M 167K271030 Holder S001 SS01020590 Slide Switch, Tray In 091M 51280308M0 B.H. Tapped Screw B3 x 8 S002 SS01020590 Slide Switch, Tray Out 095M 167K305500 Magnet (K) S004 SS01020590 Slide Switch, Push In 103M 167K160530 Buffer, Clamper S005 SS01020590 Slide Switch, Clamper Down 106M 167K358010 Bracket (K), Tray Guide S006 SS01020590 Slide Switch, Clamper Up 108M 167K259020 Bushing, Front Guide RG Ring, E Type φ1.2 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer	086M	167K056030				1	5 pg	
167K115030 Spring, Up Adj. 167K271030 Holder 091M 51280308M0 B.H. Tapped Screw B3 x 8 095M 167K305500 Magnet (K) 103M 167K160530 Bracket (K), Tray Guide 107M 64001200R0 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K12010 Shaft, Tray Guide 121M 167K056020 Buffer	1				M002	MM01200130	D.C. Motor, Tray Drive	
167K271030				33 x 10	M003	MM01200130	D.C. Motor, Clamper Driv	/e
091M 51280308M0 B.H. Tapped Screw B3 x 8 S002 SS01020590 Slide Switch, Tray Out 094M 167K005010 Clamper, Magnet Case S003 SS01020590 Slide Switch, Push In 095M 167K305500 Magnet (K) S005 SS01020590 Slide Switch, Clamper Down 103M 167K160530 Bracket (K), Tray Guide S006 SS01020590 Slide Switch, Clamper Up 106M 167K358010 Roller, Tray Guide RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide Shaft, Tray Guide 121M 167K056020 Buffer					8001	\$501020500	Clida Contact Torrett	
094M 167K005010 Clamper, Magnet Case S003 SS01020590 Slide Switch, Push In S004 SS01020590 Slide Switch, Clamper Down S005 SS01020590 Slide Switch, Clamper Up Slide Switch, Laser Safety Slide Sw				13 x 8				l
095M 167K305500 Magnet (K) 098M 167K056010 Buffer, Clamper 103M 167K160530 Bracket (K), Tray Guide 107M 64001200R0 RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K12010 Shaft, Tray Guide 121M 167K056020 Buffer S004 SS01020590 Slide Switch, Clamper Down S005 SS01020590 Slide Switch, Clamper Up S1ide Switch, Laser Safety	•			1				
098M 167K056010 Buffer, Clamper S006 SS01020590 Slide Switch, Laser Safety 103M 167K160530 Bracket (K), Tray Guide Roller, Tray Guide Roller, Tray Guide RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer				l	S004		-	wn
103M 167K160530 Bracket (K), Tray Guide 106M 167K358010 Roller, Tray Guide 107M 64001200R0 RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer			•	1			Slide Switch, Clamper Up	•
106M 167K358010 Roller, Tray Guide 107M 64001200R0 RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer				İ	S006	SS01020590	Slide Switch, Laser Safety	<i>'</i>
107M 64001200R0 RG Ring, E Type φ1.2 108M 167K259020 Bushing, Front Guide 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer				1	1	1		
108M 167K259020 Bushing, Front Guide 109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer				1.2				
109M 51280308M0 B.H. Tapped Screw B3 x 8 120M 167K112010 Shaft, Tray Guide 121M 167K056020 Buffer	, ,					[[
121M 167K056020 Buffer	1	51280308M0		3 x 8				1
				1		1		
124W 167K 160260 Bracket, Slide Bearing				I				1
	124M	10/1/100200	Bracket, Slide Bearing	1		1		l
				1				
				I	1.	ŀ		1
						ľ		1
						l		1
						1		1

ELECTRICAL PARTS LIST

ASSIGNMENT OF COMMON PARTS CODES.			
	REF. DESIG.	PART NO.	DESCRIPTION
RESISTOR R***: (1) GD05 140, Carbon film fixed resistor, ±5%, 1/4W			
R***: (2) GD05 160, Carbon film fixed resistor, ±5%, 1/6W			PD16-DEMO CIRCUIT BOARD
—Resistance value	PD16	YK158K1820	P.W. Board, Demo
Enamelas		ZZ157K8820	P.W. Board Assembly
Examples ① Resistance value			PD16-CAPACITOR
$0.1\Omega001$ $10\Omega100$ $1k\Omega102$ $100k\Omega104$ $0.5\Omega005$ $18\Omega180$ $2.7k\Omega272$ $680k\Omega684$	C502	OA10505010	Elect 1µF 50V
$1\Omega010 100\Omega101 10k\Omega103 1Mk\Omega105$	C504 C511	EA68505010 DD15270300	Elect 6.8µF 50V Ceramic 27pF ±5%
6.8Ω068 390Ω391 22kΩ223 4.7MkΩ475	C512	DD15270300	Ceramic 27pF ±5%
(Note) Please distinguish 1/4W from 1/6W by the shape of parts	C520 C521	DF15471350 DF15471350	Film 470pF ±5% Film 470pF ±5%
used actually.	552.	27.1047.1000	
C***: CERAMIC CAP.	D544		PD16-SEMICONDUCTORS
(1) DD1 ; 370, Ceramic condenser Disc type	}	HD20002000	Diode 1SS133, etc.
①① Temp. coeff. P350 ~ N1000, 50V	D549 D551	HD20002000	Diode 1SS133, etc.
Capacity value	0551	AD20002000	Diode 133133, etc.
Tolerance	Q501	HC10009490	IC SAA7210
Examples	Q502 Q503	HC10158060 HC10010490	IC μPD41416C-20 IC SAA7220
Tolerance (Capacity deviation) ±0.25pF0 -	Q504	HC10010320	IC IR2339
±0.5pF1	Q510	HT111752D0	Transistor 2SA1175(FF, EF)
±5%5	Q511 Q513	HT111752A0 HT107332A0	Transistor 2SA1175(FF, EF) Transistor 2SA733(P, Q)
 Tolerance of COMMON PARTS handled here are as follows: 0.5pF ~ 5pF±0.25pF 	Q514	HT327852D0	Transistor 2SC2785(FF, EF)
6pF ~ 10pF±0.5pF	Q530	HT327852A0	Transistor 2SC2785
12pF ~ 560pF±5% ② Capacity value	Q531 Q537	HT327852A0 HT309452A0	Transistor 2SC2785 Transistor 2SC945(Q, R)
0.5pF005 3pF030 100pF101			
1pF010 10pF100 220pF221 1.5pF015 47pF470 560pF561	J501	YP06003410	PD16-MISCELLANEOUS Plug, 2P
	3501	1700005410	riug, 2r
C***: CERAMIC CAP. (1) DK16300, High dielectric constant ceramic condenser	W201	YB00080250	Connective Cord, 15P
Disc type	W516	YB00060240	Connective Cord, 8P
Temp. chara. 2B4, 50V	X501	XB006001Q0	Crystal 11.2896MHz
Capacity value			
Example			PF16-OPTICAL OUT
① Capacity value 100pF101 1000pF102 10000pF103	0516	YK158K1830	CIRCUIT BOARD
470pF471 2200pF222	PF16	ZZ157K8830	P.W. Board, Optical Out P.W. Board Assembly
C***: ELECTROLY CAP. (本), FILM CAP. (+)	0001	HC404900B0	IC TC4049BP
(1) EA 10, Electrolytic condenser One-way lead type, Tolerance ±20%	QD02	HC404900B0	1C TC40498P
① ②	1002	YJ15000010	Jack, Receptacle with OPT Diode
Dielectric strength Capacity value	1D03	1315000010	Jack, Neceptacle With OFT Dioge
	WD01	YU04100260	Jumper Lead, 4P
Examples (i) Capacity value			
0.1μF104 4.7μF475 100μF107]		
0.33μF334 10μF106 330μF337 1μF105 22μF226 1100μF108			
2200μF228			
① Working voltage 6.3V006 25V025			
10V010 35V035			
16V016 50V050			
(2) DF15 350, Plastic film condenser			
① One-way type, Mylar ±5% 50V			
Capacity value			
Examples			
① Capacity value			
0.001μF (1000pF)102 0.1μF104 0.0018μF182 0.56μF564			
0.01μF103 1μF105			
0.015µF153			

REF. DESIG.	PART NO.		DESCRIPTI	ON
PM16	W8157K1410 ZZ157K8410	PM16-FEAT CIRCUIT BO P.W. Board, P.W. Board	OARD Feature U-0	
CF11	DK56331300	PM16-CAPA Ceramic	CITOR	tion ohio
CF12	DD55331300	Ceramic		±10%, Chip ±5%, Chip
CF13	DK56331300	Ceramic	330pF	
CF21	DK56331300	Coromia	22005	,
CF29	DK36331300	Ceramic	330pF	±10%, Chip
CF38			_	٠,
. } CF43	DK56331300	Ceramic	330pF	±10%, Chip
CF43 CF50	OA22703510	Elect	220µF	. 35V
	Onez.	Elect	e÷4m.	. 354
CF61			***	*
CF67	DK56331300	Ceramic .	330pF	±10%, Chip
CF85	DK56331300	Ceramic	330pF	±10%, Chip
CF87				
CF91	DK56331300	Ceramic	330pF	±10%, Chip
CM01	OA47601610	Elect	47µF	16V
- 1	1	PM16-RESIS		* * *****
RF01	NI05022110	(All Resistor 2.2Ω, C		nd 1/10vv)
RF14	NI05103110	10ΚΩ, 0	-	1
RF15	NI05103110	10ΚΩ, 0	Chip	1
RF16	NI05103110	10ΚΩ, C	Chip	1
RF19	NI05103110	10KΩ, C	*	1
RF20	NI05103110 NI05104110	10KΩ, C		1
RF22	NI05104110 NI05104110	100KΩ, C 100KΩ, C		1
RF23	NI05022110	2.2Ω, 0		1
RF24	NI05022110	2.2Ω, C		
RF26	NI05102110	1ΚΩ, C	*bio	1
RF27	NI05100110	10Ω, C		!
RF28	NI05222110	2.2KΩ, C	hip	
RF29	NI05100110	10Ω, C	Chip	
RF30	NI05102110	1KΩ, C	*	
RF50	NI05102110 NH05010140	1KΩ, C 1Ω	+	xw l
RF51	NI05102110	1Ω 1KΩ, C	-	444
	:		•	
0501		PM16-SEMIC		
DF01 DF02	HZ20003020 HZ30002050	Diode Zener	MA151K, 0	
DF03	HZ20001020		02CZ5.1V(MA151WK	
DF05	HZ20001020		MA151WK	
DF50	HD20003000	Diode	RL103F	
DF51	HD30561000	Zener	5.6V	
DM01	HZ30005050	Zener	02CZ6.8, C	*hio
DM02	HZ30004050		02CZ8.2, C	-
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REF.	T	T
DESIG.	PART NO.	DESCRIPTION
QF01	HC10016260	IC MSM80C59
QF02	HC10015260	IC MSM80C51
QF03	HC10011000	IC MSM2816A
QF06	BA20002020	Semicon Composit UN2214, Chip
QF07	BA20002020	Semicon Composit UN2214, Chip
QF08	BA20002020	Semicon Composit UN2214, Chip
QF10	8A20002020	Semicon Composit UN2214, Chip
QM01 QM02	HC10148030 HC10148030	IC LB1645N IC LB1645N
		PM16-MISCELLANEOUS
JF01 JF02	YJ06006330	Jack, 13P
JF03	YJ06006250 YP06004420	Jack, 5P
JF10	YP06001050	Plug, 14P Plug, 5P
LM01	LC14730040	Choke Coil 47µH
WF03	YB00700250	Connective Cord, 14P
W202	YB00080240	Connective Cord, 7P
W515	YB00390120	Connective Cord, 3P
XF01	FQ01205030	Seramic Vibrator, 12.0MHz
XF02	FQ01205030	Seramic Vibrator, 12.0MHz
		PP16-DAC CIRCUIT BOARD
PP16	YK158K1310	P.W. Board, DAC
	ZZ157K8310	P.W. Board Assembly
		PP16-CAPACITORS
C551	OA47601650	Elect 47µF 16V
C552	OF15473010	Film 0.047µF ±5%
C556	0515224010	F11 0.00 F 45W
C569	OF15224010	Film 0.22µF ±5%
C570	DF15681350	Film 680pF
C571	OF15473010	Film 0.047µF ±5%
C572	OF15473010	Film 0.047µF ±5%
C573	OA47602550	Elect 47µF 25V
C574	OA47602550	Elect 47µF 25V
C575	OA10601650	Elect 10µF 16V
C576	OA10601650	Elect 10µF 16V
C580	OF54222520	Film 2200pF ±2%
C581	OF54222520	Film 2200pF ±2%
C582 C583	DF74153520	Film 0.015µF ±2%
C584	DF74153520 OF54512510	Film 0.015µF ±2% Film 5100pF ±2%
C585	OF54512510	Film 5100pF ±2%
C586	OF54222510	Film 2200pF ±2%
C587	OF54222510	Film 2200pF ±2%
C588	OF54102520	Film 1000pF ±2%
C589	OF54102520	Film 1000pF ±2%
C590	OA10702510	Elect 100µF 25V
C591	OA10702510	Elect 100µF 25V
C592 C593	OA10601610	Elect 10µF 16V
C593	OA10601610 OA10702550	Elect 10µF 16V Elect 100µF - 25V
C597	OA10702550	Elect 100µF 25V
C598	OA10702550	Elect 100µF 25V
C599	OA10702550	Elect 100µF 25V
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REF. DESIG.	PART NO.		DESCRIPT	ION	REF. DESIG.	PART NO.		DESCRIPTION	
∆ C805	OB68802510	Elect	6800µF	= 25V	D821	HD30024060	Zener	6.8V	
₾ C806	OB68802510	Elect	6800µF	25V	△ D831	HD20005010	Diode	W06B	
C807	OA47602550	Elect	47µF	= 25V	△ D832	HD20005010	Diode	W06B	
C808	OA47602550	Elect	47µF		⊉D833	HD20005010	Diode	W06B	
C811	OA47702550	Elect	470µF		△ D834	HD20005010	Diode	W06B	1
C812	OA47702550	Elect	470µF		△ D841	HD20009010	Diode	U05B	1
▼ C836	OA33802520	Elect	3300µF		△ D842	HD20009010	Diode	U05B	1
∆ C837	OA33802520	Elect	3300µF		△ D843	HD20009010	Diode	U05B	
∆ C845	OA68801620	Elect	6800µF	= 16V	△ D844	HD20009010	Diode	U05B	
		PP16-RESIS	STORS		QN01	HT107332A0	Transistor	2SA733(P, Q)	;
R560	GM21417810	1.78ΚΩ	±2%	%W	QN02	HT112962A0	Transistor	2SA1296(Y, GR)	
R561	GM21417810	1.78ΚΩ	±2%	%W	QN03	HT309452A0	Transistor	2SC945(Q, R)	
R562	GM21410010	1ΚΩ	±2%	%W					
R563	GM21410010	1ΚΩ	±2%	%W	Q551	HC10011490	IC	TDA1541	
R568	GM21423710	2.37ΚΩ	±2%	%W	Q552	HC10027090	IC	NJM5534	
R569	GM21423710	2.37ΚΩ	±2% +2%	%W	Q553	HC10027090	IC	NJM5534	
R570 R571	GM21423710 GM21423710	2.37KΩ 2.37KΩ	±2% ±2%	%W %W	Q554	HC10027090	IC	NJM5534	
∆ R580	GWI21423710	2.57846	-270	A ***	Q555	HC10027090	IC	NJM5534	
Δ N360	NH05033140	3.3Ω	±5% %w	, Fusible [N,A,W]	Q556 Q557	HF203722A0 HF203722A0	F.E.T. F.E.T.	2SK372(GR, BL)	
∆ R583	111103033140	0.54	~~~ A.	, . asibic (14,74,11)	4557	HF203722A0	F.E.1.	2SK372(GR, BL)	
			_		Q801	HT403131D0	Transistor	2SD313(D)	
△ R801	NH05010120	1Ω	±5%	1/2W, Fusible	Q802	HT309452A0	Transistor	2SC945(Q, R)	
∆ R802	NH05010120	1Ω	±5%	1/2W, Fusible	Q803	HT107332A0	Transistor	2SA733(P, Q)	
₫ 8803	NH05010140	1Ω	±5%	¼W, Fusible	Q804	HT205071D0	Transistor	2SB507(D)	
∆ R804	NH05010140	1Ω	±5%	1/2W, Fusible	Q805	HT327852A0	Transistor	2SC2785(RF, JF)	
R807	GM21456200	562Ω	±2%	%W	Q806	HT111752A0	Transistor	2SA1175(RF, JF)	
R808	GM21456200	562Ω	±2% +2%	%W	Q821	HT113582A0	Transistor	2SA1358(O, Y)	
R809 R810	GM21438310 GM21438310	3.83KΩ 3.83KΩ	±2% ±2%	%W %W	1 5044	EC10200000	F		
R813	GM21412110	1.21ΚΩ	±2%	%W	∆F841	FS10200800	Fuse		
R814	GM21412110	1,21ΚΩ	±2%	%W	JB21	YT02020550	Terminal, II	N/OUT- 2P	
1014	GWZ1412110	1.211		7.11	JD20	YT02010320	Terminal, 1		
R815	GM21414710	1.47ΚΩ	±2%	%W	JG01	YL01010110	Terminal, E		
R816	GM21414710	1.47ΚΩ	±2%	%W	JG02	YJ08000270	Jack, Fuse		
R817	GM21412110	1.21ΚΩ	±2%	1/4W			,		
R818	GM21412110	1.21ΚΩ	±2%	1/4W	J510	YJ06006240	Jack, 4P		
∆ R821	NH05010120	1Ω	±5%	1/2W, Fusible	J511	YP06003330	Plug, 3P		
R822	GM21410010	1ΚΩ	±2%	%W	J515	YJ06006230	Jack, 3P		
△ R831	NH05010120	1Ω	±5%	1/2W, Fusible	J516	YJ06006280	Jack, 8P		
∆ R832	NH05010120	1Ω	±5%	½W, Fusible	J519	YT02020290	Terminal, A	ludio Out	
		PP16-SEMI	CONDUCT	ORS	J524	YJ06002440	Jack, 4P		
DB01	HD20001000	Diode	1S2473	Ons	J010	YJ06001050	Jack, 5P		
5501	11020001000	2.000	102470		J011	YJ06001070	Jack, 7P		
DN01					1				
1	HD20001000	Diode	152473		J801	YP06001070	Plug, 9P		
DN06					J802	YJ06002450	Jack, 6P		
DN08	HD20001000	Diode	152473		J803	YP06003340	Plug, 9P		
DN09	HD20001000	Diode	152473	BD3 0EB1		Theresian	D. 100 -	4	
DN10	HD30063060 HD30063060	Zener Zener	3.9V 3.9V	RD3.9EB1 RD3.9EB1	LD01	TP41042010	Pulse Trans		
DN11	11230003000	201101	J.J ¥	1100.0401	L502	LY20045010	Relay	SZ-2101	
D801	HD20005010	Diode	W06B			1			
D802	HD20005010	Diode	W068				PP26-REGI	ULATOR	
D803	HD20005010	Diode	W06B			1	CIRCUIT E		
D804	HD20005010	Diode	W06B		PP26	YK158K1320	P.W. Board		
D805	HD30015060	Zener	5.6V			ZZ157K8320	P.W. Board	Assembly	
D806	HD30015060	Zener	5.6V					100470	
△ D807	HD20005010	Diode	W068		D845	HD20001000	Diode	1S2473	
∆ D808	HD20005010	Diode	W06B W06B		A 0824	HC10044060	ıc	μPC7912H	
△ D809 △ D810	HD20005010 HD20005010	Diode Diode	WO6B		∆ Q831 ∆ Q832	HC10044060 HC10043060	IC	μPC7912H μPC7812H	
A D010	11020003010	Diode	******	•	∆ Q841	HC10056060	lic	μPC7805H	
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REF. DESIG.	PART NO.	DESCRIPTION
W803	Y800060240	Connective Cord, 9P
PP36	YK158K1330	PP36-POWER SWITCH CIRCUIT BOARD [F] P.W. Board, Power Switch [F]
∆ GH01 ∆ SH01	DF16104510 SP01010650	Film Cap. 0.1µF 200V [F] Push Switch, Power [F]
PR16	YK158K1880 ZZ157K8880	PR16-HEADPHONE AMP CIRCUIT BOARD P.W. Board, Headphone Amp P.W. Board Assembly
R900	RM01030340	Variable Resistor 10KΩ(A)
Q901 Q903 Q904 Q905 Q906	HC10016090 HT328781A0 HT328781A0 HT328781A0 HT328781A0	IC NJM4556D Transistor 2SC2878 Transistor 2SC2878 Transistor 2SC2878 Transistor 2SC2878
J901	YJ01002340	Jack, Headphone
W510 W511	Y800230300 Y800500420	Connective Cord, 4P Connective Cord, 3P
PS16	YK158K1850 ZZ157K8850 DK18103840	PS16-POWER SWITCH CIRCUIT BOARD (A, N, W) P.W. Board, Power Switch P.W. Board Assembly Ceramic Cap. 0.01µF 400V (N,A,W)
\$SH01	SP01010650	Push Switch, Power [N, A, W]
PS26	YK157K0510 ZZ157K8510	PS26-TEN KEYS CIRCUIT BOARD P.W. Board, Ten Keys P.W. Board Assembly
SS01 }	SP01010970	Push Switch
SS15 SS16	SS02020850	Slide Switch, Timer/Play
PV16	YK158K1810 ZZ157K8810	PV16-SERVO CIRCUIT BOARD P.W. Board, Servo P.W. Board Assembly
C201 C204 C257 C271 C273 C279	OA47602510 OA10505010 EQ47503530 OA47601610 OA10505010 OA10601610	PV16-CAPACITOR Elect 47μF 25V Elect 1μF 50V Elect 47μF 16V Elect 1μF 50V Elect 10μF 16V
; }		

REF. DESIG.	PARINU.	DESCRIPTION
	1	
[PV16-RESISTORS
R211	GM11656240	5.62MΩ ±1% 1/6W
R212	GM11656240	5.62MΩ ±1% 1/6W
R231	NH05100140	10Ω ±5% ¼W, Fusible
R232	NH05100140	10Ω ±5% %W, Fusible
R233	NH05121140	120Ω ±5% ¼W, Fusible
R234 R254	MH05121140 GM11690920	120Ω ±5% ½W, Fusible 90.9KΩ ±1% 1/6W
R274	GM11613020	13KΩ ±1% 1/6W
R275	GM11690920	90.9KΩ ±1% 1/6W
R277	GM11635730	357KΩ ±1% 1/6W
R282	NH05100140	10Ω ±5% ½W, Fusible
l		BY 15 SEMICONDUCTORS
D253	HD30751000	PV16-SEMICONDUCTORS Zener 7.5V
D271	11000751000	251161 7.54
1 7	HD20002000	Diode 1SS133, etc.
0275		
Q201	HC10003090	IC NJM4558D
Q202 Q203	HT107332A0 HT309452A0	Transistor 2SA733(P, Q)
Q204	HT334212A0	Transistor 2SC945(Q, R) Transistor 2SC3421(O, Y)
Q205	HT113582A0	Transistor 2SA1358(O, Y)
0231	HT113582A0	Transistor 2SA1358(O, Y)
Q232	HT334212A0	Transistor 2SC3421(O, Y)
Q233	HC10011320	IC IR3741
Q251	HC10003090	IC NJM4558D
Q252	HT107332A0	Transistor 2SA733(P, Q)
0253	HT309452A0	Transistor 2SC945(Q, R)
Q254	HT107332A0	Transistor 2SA733(P, Q)
Q255	HT309452A0	Transistor 2SC945(Q, R)
Q256	HT309452A0	Transistor 2SC945(Q, R)
0271	HC10017260	IC 80C51
Q272	HT309452A0	Transistor 2SC945(Q, R)
		PV16-MISCELLANEOUS
J201	YJ06006350	Jack, 15P
J202	YJ06006280	Jack, 8P
J203	YP06003350	Plug, 14P
J205	YP07002270	Plug, 16P
J206	YP07002270	Plug, 16P
L231	LC14730040	Choke Coil 47µH
L232	LC14730040	Choke Coil 47µH
W802	YU06080260	Jumper Lead, 6P
		PV26-SERVO MODULE
		CIRCUIT BOARD
PV26	WB157K1430	P.W. Board, Servo Module
	ZZ157K8430	P.W. Board Assembly
		PV26-CAPACITORS
C301	DF74682520	Film 6800pF ±2%
C302	DF74682520	Film 6800pF ±2%
C305	DF74562520	Film 5600pF ±2%
C306	DF74562520	Film 5600pF ±2%
C308	DD55391300 OA33601610	Ceramic 390pF ±5% Elect 33µF 16V
C310	DF74681520	Elect 33µF 16V Film 680pF ±2%
C311	DF74182520	Film 1800pF ±2%
C312	DF74682520	Film 6800pF ±2%
C314	DF74682520	Film 6800pF ±2%
C315	DF74682520	Film 6800pF ±2%
C316	DK46104200	Ceramic 0.1µF ±10%, Chip

PV28-RESISTORS (All Resistors set :55% and 1/10W) 10KΩ 11KΩ, Chip 13KΩ, Chip 10KΩ, C	REF. DESIG.	PART NO.	DESCRIPTION	REF	PARING	DESCRIPTION
R300 NI01103110 IOKn						4
R300 NI01103110 10Kn	1			. ,		
R301 NI01103110 10K.G. ±1%, Chip R370 NI0193110 3K.G. ±1%, Chip R371 NI0193110 3K.G. ±1%, Chip R371 NI0193110 3K.G. ±1%, Chip R372 NI0193110 3K.G. ±1%, Chip R372 NI0193110 3K.G. ±1%, Chip R373 NI0193110 3K.G. ±1%, Chip R374 NI0193110 3K.G. ±1%, Chip R375 NI0193110 3K.G. ±1%, Chip R375 NI0193110 3K.G. ±1%, Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip NI0193110 3K.G. Chip R376 NI0193110 3K.G. Chip NI0193110 NI0193110 3K.G. Chip NI0193110 NI0193110 3K.G. Chip NI0193110 R300	NI01103110					
R302 NI01272110 Z,7KG ±1%, Chip R371 NI01383110 38KG ±1%, Chip R372 NI0103110 38KG ±1%, Chip R373 NI01032110 38KG ±1%, Chip R374 NI01032110 38KG ±1%, Chip R373 NI01032110 38KG ±1%, Chip R374 NI01032110 38KG ±1%, Chip R374 NI01032110 38KG ±1%, Chip R375 NI05072110 27KG ±1%, Chip R376 NI05072110 27KG ±1%, Chip NI05072110 27KG ±1%, Chip R376 NI05072110 27KG ±1%, Chip NI05072110						
R306 NI05322110 2.2KG, Chip R373 NI05322110 3.80KG	•	NI01272110		1 1		
R307 NI0103110 10KΩ	R303		470Ω ±1%, Chip			3.9KΩ ±1%, Chip
R309 NI01103110 10KG						
R308 NI01272110 2,7KG, ±1%, Chip R375 NI05472110 33KG, Chip R379 NI05472110 2,7KG, Chip R379 NI05533110 33KG, Chip R379 NI05472110 2,7KG, Chip R379 NI05533110 2,7KG, Chip R379 NI05533110 2,7KG, Chip R379 NI05533110 2,7KG, Chip R379 NI05472110 2,7KG, Chip R						
R319 NI05222110				6 1		'
R310 NI05223110 2.2KG, Chip R336 NI05333110 33KG, Chip R337 NI05333110 33KG, Chip R338 NI05422110 NIOS503110 NKG, Chip R338 NIOS503110 A7KG, Chip R338 NIOS503110				""	141034/2110	4.7K12, Chip
R311 NIOS103110 10K.R. Chip R380 NIOS273110 4.7K.R. Chip R381 NIOS683110 10K.R. Chip R381 NIOS683110 68K.R. Chip R382 NIOS63110 4.7K.R. Chip R382 NIOS673110 4.7K.R. Chip R385 NIOS673110 4.7K.R. Chip R386 NIOS673110 4.7K.R. Chip R386 NIOS673110 4.7K.R. Chip R386 NIOS673110 4.7K.R. Chip R386 NIOS673110 4.7K.R. Chip R387 NIOS673110 4.7K.R. Chip R388 NIOS673110 4.7K.R. Chip R388 NIOS673110 4.7K.R. Chip R388 NIOS673110 4.7K.R. Chip R388 NIOS673110 4.7K.R. Chip R389 NIOS673110 4.7K.R. Chip R380 NIOS673110 4.7K.R. Chip R380 NIOS673110 4.7K.R. Chip R380 NIOS673110				R376	NI05333110	33KΩ, Chio
R313 NIOSS63110 DICK_C, Chip R381 NIOSS63110 ATK_C, Chip R382 NIOSS72110 ATK_C, Chip R386 NIOS72110 ATK_C, Chip R386 NIOS72110 ATK_C, Chip R386 NIOS72110 ATK_C, Chip R386 NIOS72110 ATK_C, Chip R388 NIOS72110 ATK_C, Chip R398 NIOS72110 TSK_C ±1%, Chip R399 NIOS73110 TSK_C ±1%, Chip R399 NIOS523110 TSK_C, Chip				R379	NI05273110	
R313 NIOSE83110 GR.C., Chip R386 NIOS472110 A7K.C., Chip R385 NIOS472110 A7K.C., Chip R386 NIOS473110 A7K.C., Chip R387 NIOS473110 A7K.C., Chip R387 NIOS473110 A7K.C., Chip R388 NIOS473110 A7K.C., Chip R389 NIOS473110 A7K.C., Chip R399 NIOS473110 A7K.C., Chip A7K.C	R311		10KΩ, Chip			4.7KΩ, Chip
R314 NIOS473110 47K.R. Chip R386 NIO1273110 27K.R. ±1%, Chip R316 NIOS473110 47K.R. Chip R388 NIOS473110 47K.R. Chip R317 NIOS473110 47K.R. Chip R388 NIOS473110 47K.R. Chip R318 NIOS473110 47K.R. Chip R318 NIOS473110 47K.R. Chip R318 NIOS473110 47K.R. Chip R318 NIOS473110 37K.R. ±1%, Chip R320 NIO1133110 330K.R. ±1%, Chip R320 NIO1753110 75K.R. ±1%, Chip R321 NIO1334110 330K.R. ±1%, Chip R322 NIO5182110 1.5K.R. Chip R325 NIO5182110 1.5K.R. Chip R325 NIO5182110 22K.R. Chip R325 NIO5223110 22K.R. Chip R328 NIOS223110 22K.R. Chip R329 NIOS563110 56K.R. Chip R329 NIOS563110 56K.R. Chip R329 NIOS563110 A70R. Chip R323 NIOS471110 A70R. Chip R323 NIOS822110 S2K.R. Chip R324 NIOS471110 A70R. Chip R325 NIOS623110 S2K.R. Chip R326 NIOS623110 S2K.R. Chip R326 NIOS623110 S2K.R. Chip R326 NIOS471110 A70R. Chip Canada NIOS623110 Canada NIOS623110 Canada NIOS623110 Canada NIOS623110 Canada NIOS623110 Canada NIOS623110 Canada Canada NIOS623110 Ca						1
R315 NIO5473110 47K.R. Chip R336 NIO1843110 180K.R. ±1%, Chip R316 NIO5473110 47K.R. Chip R317 NIO5473110 47K.R. Chip R318 NIO5473110 47K.R. Chip R328 NIO1582110 13K.R. ±1%, Chip R329 NIO1582110 330K.R. ±1%, Chip R329 NIO1753110 75K.R. ±1%, Chip R329 NIO1753110 75K.R. ±1%, Chip R324 NIO5182110 1.5K.R. Chip R325 NIO5182110 1.5K.R. Chip R326 NIO5223110 22K.R. Chip R326 NIO5223110 22K.R. Chip R328 NIO5223110 22K.R. Chip R329 NIO5533110 S6K.R. Chip R329 NIO553110 S6K.R. Chip R329 NIO553110 R320 NIO5471110 R321 NIO5473110 R321 NIO5473110 R321 NIO5473110 R322 NIO553110 R323 NIO5471110 R324 NIO5473110 R325 NIO5823110 R326 NIO5473110 R326 NIO5473110 R327 NIO5473110 R328 NIO5473110 R329 NIO5473110 R329 NIO5473110 R320 NIO5473						
R316 NIO5472110 47KG, Chip 74KG, Chi						
R318 NI05863110 AFK.Ω, Chip BASB NI05873110 AFK.Ω, Chip BASB NI05803110 BASC ATM, Chip BASB NI05103110 TSKΩ ±1%, Chip DASD ±100000000000000000000000000000000000			, ,			
R318 NIOS683110 SeKΩ, Chip R399 NIOS104110 100KΩ, Chip R391 NIOS104110 30KΩ ±1%, Chip R393 NIOS104110 30KΩ ±1%, Chip R393 NIOS104110 30KΩ ±1%, Chip R393 NIO1334110 30KΩ ±1%, Chip R394 NIO1334110 30KΩ ±1%, Chip R395 NIO1334110 30KΩ ±1%, Chip R395 NIO1343110 30KΩ ±1%, Chip R396 NIO5223110 22KΩ, Chip R398 NIO5104110 100KΩ, Chip R397 NIO5473110 47KΩ, Chip 47KΩ, Chip R398 NIO5473110 47KΩ, Chip R399 NIO5473110 R308 NIO5823110 82KΩ, Chip R399 NIO5473110 R308 NIO5823110 82KΩ, Chip R399 NIO5473110 R308 NIO5823110 R3						
R320 NI0133110 S.K.Ω			· ·			1
R321 NI01133110 13Kff ±1%, Chip R391 NI01753110 75Kff ±1%, Chip R391 NI01753110 75Kff ±1%, Chip R392 NI0152110 1.5Kff, Chip R395 NI01524110 22Kff, Chip R397 NI05223110 22Kff, Chip R397 NI0523110 22Kff, Chip R398 NI05543110 47Kff, Chip 47Kff, Chip 47Kff, Chip 47Kff, Chip 47Kff, Chip R393 NI05471110 4700, Chip R393 NI05471110 4700, Chip R393 NI05471110 4700, Chip R394 NI05471110 4700, Chip R393 NI05471110 4700, Chip R394 NI05471110 4700, Chip R394 NI05471110 4700, Chip R395 NI05823110 82Kff, Chip R395 NI05823110 82Kff, Chip R395 NI05823110 82Kff, Chip R395 NI05823110 82Kff, Chip R396 R396 R399 NI05823110 R396 R396 R399 R						
R323 NI01324110 R30KΩ ±1%, Chip R394 NI01324110 R30KΩ ±1%, Chip R325 NI05182110 1.5KΩ, Chip R395 NI05223110 22KΩ, Chip R397 NI05223110 22KΩ, Chip R397 NI05223110 22KΩ, Chip R398 NI05233110 R326 NI05543110 S6KΩ, Chip R397 NI05543110 S6KΩ, Chip R398 NI05473110 A70Ω, Chip R331 NI05471110 A70Ω, Chip R331 NI05471110 A70Ω, Chip R331 NI05471110 A70Ω, Chip R3331 NI05471110 A70Ω, Chip R3331 NI05471110 A70Ω, Chip R3331 NI05471110 A70Ω, Chip R334 NI05471110 A70Ω, Chip R335 NI05833110 R3KΩ, Chip R335 NI05833110 R3KΩ, Chip R336 NI05833110 R3KΩ, Chip R337 NI0134110 R30KΩ ±1%, Chip R338 NI05833110 R30KΩ, Chip R338 NI05833110 R30KΩ, Chip R339 NI05233110 R30KΩ, Chip R339 NI05233110 R30KΩ, Chip R339 NI05543110 R30KΩ, Chip R339 NI05104110 R30KΩ, Chip R349 NI05543110 R30KΩ, Chip R349 NI05543110 R30KΩ, Chip R349 NI05823110 R30KΩ, Chip R350 NI0583110 R30KΩ, Chip R350 NI0583110 R36KΩ, Chip R350	R321	NI01133110	13KΩ ±1%, Chip	R390	NI01753110	75KΩ ±1%, Chip
R324 NIO5182110 L,5KΩ, Chip R396 NIO5102110 L2KΩ, Chip R396 R396 NIO5102110 L2KΩ, Chip R396 R397 NIO5102110 L2KΩ, Chip R397 R397 R397 R398						
R325 NIO5152110 1,5K.Ω, Chip R396 NIO5124110 120KΩ, Chip R397 NIO5223110 22KΩ, Chip R397 NIO5223110 22KΩ, Chip R398 NIO5473110 120KΩ, Chip 47KΩ, Chip 47				1		, ,
R326 NI05223110 22KΩ, Chip R397 NI05124110 120KΩ, Chip R327 NI0523110 22KΩ, Chip R398 NI0523110 56KΩ, Chip R398 NI05563110 56KΩ, Chip R398 NI05563110 47ΩΩ, Chip R331 NI05471110 47ΩΩ, Chip R332 NI05471110 47ΩΩ, Chip R333 NI05471110 47ΩΩ, Chip R333 NI05471110 47ΩΩ, Chip R334 NI05471110 47ΩΩ, Chip R334 NI05471110 47ΩΩ, Chip R334 NI05471110 47ΩΩ, Chip R334 NI0547110 47ΩΩ, Chip R334 NI05472110 82KΩ, Chip R335 NI05823110 82KΩ, Chip R336 NI05823110 S6KΩ, Chip R336 NI0523110 S6KΩ, Chip R338 NI05563110 S6KΩ, Chip R339 NI055472110 10KΩ, Chip R334 NI05472110 470KΩ, Chip R334 NI05472110 470KΩ, Chip R346 NI05472110 470KΩ, Chip R346 NI05472110 470KΩ, Chip R346 NI05472110 470KΩ, Chip R346 NI05823110 S6KΩ, Chip R346 NI05823110 S6KΩ, Chip R347 NI05633110 S6KΩ, Chip R348 NI05822110 S6KΩ, Chip R358 NI05822110 S6KΩ, Chip R359 NI05822110 S6KΩ, Chip R359 NI05822110 S6KΩ, Chip R359 NI05822110 S6KΩ, Chip R359 NI05822110 S6KΩ, Chip R350 NI05822110 S6KΩ, Chip R350 NI05822110 S6KΩ, Chip R351 NI05822110 S6KΩ, Chip R350 NI05822110 S6KΩ, C						
R327 NIO5223110 22KΩ, Chip R338 NIO5473110 47KΩ, Chip 47CΩ, Chip 4						
R328 NIO5563110 S6KΩ, Chip S6KΩ, Ch						
R329 NIO5563110 470Ω, Chip 2001 2						
R331 NIO5871110 820Ω, Chip D301 HZ30003050 Zener 2.4V, Chip Diode MA151WK, Chip Diode MA153, Chip Diode MA151K, Chip Diode MA	R329		56KΩ, Chip			
R332 NI05821110 820Ω, Chip D302 H220001020 Diode MA151WK, Chip D304 H220005020 Diode MA151WK, Chip D304 H220005020 Diode MA153, Chip D304 H220005020 Diode MA153, Chip D305 H230002050 Diode MA153, Chip D306 H230002050 Diode MA153, Chip D306 H230002050 Diode MA153, Chip D306 H230002050 Diode MA151K, Chip D306 Diode MA151K, Chip D306 H230002050 Diode MA151K, Chip D306 H23000200 Diode MA151K, Chip D306 H230002050 Diode MA151K, Chip D306 H23000200 Diode MA15K, Chip D306 H23000200 Diode M2300020 Diode M2300020 Diode M2300200 Diode M2300200 Diode M230020 Diode M230020 Diode M2300200 Diode M23						
R333 NI05152110 1.5KΩ, Chip D304 H220005020 Diode MA151WK, Chip D305 H230002050 Diode MA153, Chip D306 H230002050 Diode MA151K, Chip D306 H230002050 Diode MA153, Chip D306 H230002050 Diode MA151K, Chip D306 H230002050 Diode MA151K, Chip D306 H23000200 D306 H23000200 D306 H23000200 D306 H23000200 D306 H23000200 D306 H2300200 D306						
R333	H332	N105821110	82012, Chip			
R334 NI05471110 470Ω, Chip D306 HZ30002060 Diode MA151K, Chip D306 HZ30002060 Diode MA151K, Chip D306 HZ30003020 Diode MA151K, Chip D306 HZ3003020 Diode MA151K, Chip D306 HZ3003020 Diode MA151K, Chip D306 HZ30003020 Diode MA151K, Chip D306 HZ3003020 Diode MA151K, Chip D306 HZ3003020 Diode MA151K, Chip D306 HZ3003020 D306 HZ300302	R333	NI05152110	1.5KQ. Chio			
R335 NIOS823110 82KΩ, Chip G8KΩ, Chip G301 HC10042090 IC NJM2902M IC						
R336 NI05683110 68KΩ, Chip C301 HC10042090 IC NJM2902M R338 NI05233110 22KΩ, Chip C302 HC10042090 IC NJM2902M R338 NI05233110 22KΩ, Chip C303 HC10042090 IC NJM2902M R340 NI05104110 100KΩ, Chip C305 HC40300020 IC NJM2901M R341 NI05474110 470KΩ, Chip C305 HC4030020 IC NJM2901M R342 NI05103110 10KΩ, Chip C305 HC4030020 IC NJM2901M R343 NI05472110 4.7KΩ, Chip C306 HC40530020 IC NJM4558M HC40530						, , ,
R338	R336	NI05683110	68KΩ, Chip	1		,
R339						
R340 NI05104110 100KΩ, Chip Chip						
R341 NIO5474110 470 κΩ, Chip Close						
R342 NI05103110 10 κΩ, Chip Case						
R343 NI05472110 4.7KΩ, Chip C308 HC10011090 IC NJM4558M C308 HX32351010 Transistor 2SC2351, Chip C309 HC10059210 IC FMW1 C311 HC10059210 IC FMW1 FMM1 FM						
R345 NI05682110 6.8KΩ, Chip Q309 HC10059210 IC FMW1 R346 NI05474110 470ΚΩ, Chip Q311 HC10059210 IC FMW1 R347 NI05104110 100ΚΩ, Chip Q312 HX111621A0 Transistor 28.1162(G), Chip R348 NI05832110 8.2ΚΩ, Chip Q314 BA20005020 Semicon Caomposit UN2210, Chip R351 NI05822110 8.2ΚΩ, Chip Q316 HX310091A0 Transistor 2SC2712(G), Chip R352 NI05683110 56ΚΩ, Chip Q316 HX310091A0 Transistor 2SC1009, Chip R355 NI05563110 56ΚΩ, Chip Q318 BA20005020 Transistor 2SC1009, Chip R357 NI05105110 1MΩ, Chip J301 YJ07002230 Jack, 16P R358 NI01364110 360ΚΩ ±1%, Chip J302 YJ07002230 Jack, 16P R360 NI01682110 6.8ΚΩ ±1%, Chip X201 FQ01205030 Seramic Vibrator 12.0MHz			70.400, 0.400			
R346 NI05474110 470ΚΩ, Chip 100ΚΩ,	R343	NI05472110	4.7KΩ, Chip	G308	HX32351010	
R347 NI05104110 100KΩ, Chip 33KΩ, Chip 3316 HX327121A0 HX327121A0 Transistor 2SC112(G), Chip Transistor 2SC2712(G), Chip Transistor 2SC1009, Chip Semicon Composit UN2210,		NI05682110				
R348				0311	HC10059210	IC FMW1
R349 NI05822110 8.2KΩ, Chip R351 NI05822110 8.2KΩ, Chip R352 NI05683110 68KΩ, Chip G316 H3310091A0 Transistor 2SC2712(G), Chip R355 NI05563110 56KΩ, Chip G317 H3310091A0 Transistor 2SC1009, Chip G318 BA20005020 Semicon Composit UN2210, Chip Transistor 2SC1009, Chip Transistor 2SC1009, Chip G318 BA20005020 Semicon Composit UN2210, Chip Transistor 2SC1009, Chip Transistor 2SC1009, Chip G318 BA20005020 Semicon Composit UN2210, Chip Transistor 2SC1009, Chip Transistor 2SC1009, Chip Transistor 2SC1009, Chip Transistor 2SC1009, Chip Semicon Composit UN2210, Chip Transistor 2SC1009, Chip Tran				0212	HY111621AA	Tenerimos SCALLEGICO ONIO
R351 NI05822110 8.2 KΩ, Chip G8KΩ, Chip G8KΩ, Chip G315 HX327121A0 Transistor 2SC2712(G), Chip Transistor 2SC1009, Chip HX310091A0 Transistor 2SC1009, Chip Transistor 2SC1009, C						
R352 NI05683110 68KΩ, Chip 56KΩ, Chip 56KΩ, Chip 77 7318 77 7318 7319 74 74 74 74 74 74 74 7						
R355 NI05563110 S6KΩ, Chip 24KΩ ±1%, Chip 24KΩ ±1%, Chip D318 BA20005020 Semicon Composit UN2210, Chip S6KΩ, Chip S6KΩ, Chip S6KΩ, Chip S6KΩ, Chip S6KΩ, Chip S6KΩ, Chip S6KΩ ±1%,						
R357 NI05105110 1MΩ, Chip 360KΩ ±1%, Chip 360KΩ ±1%, Chip J301 J301 J302 J304, 16P J304, 16P J305 J305 J306, 16P J306, 1				Q317	HX310091A0	
R358 NI01364110 360KΩ ±1%, Chip J301 YJ07002230 Jack, 16P J302 YJ07002230 J302	R356	NI01243110	24KΩ ±1%, Chip	Q318	BA20005020	Semicon Composit UN2210, Chip
R358 NI01364110 360KΩ ±1%, Chip J301 YJ07002230 Jack, 16P J302 YJ07002230 J302	R357	NI05105110	1MΩ, Chip		1	PV26-MISCELLANEOUS
R360 NI01682110 6.8KΩ ±1%, Chip X201 FQ01205030 Seramic Vibrator 12.0MHz R362 NI01823110 82KΩ ±1%, Chip R363 NI01823110 82KΩ ±1%, Chip R364 NI05472110 4.7KΩ, Chip R364 NI05472110 4.7KΩ, Chip						Jack, 16P
R361 NI01682110 6.8KΩ ±1%, Chip X201 FQ01205030 Seramic Vibrator 12.0MHz R362 NI01823110 82KΩ ±1%, Chip R364 NI05472110 4.7KΩ, Chip R364 NI05472110 4.7KΩ, Chip	R359	NI05223110		J302	YJ07002230	Jack, 16P
R362 NI01823110 82KΩ ±1%, Chip R363 NI01823110 82KΩ ±1%, Chip R364 NI05472110 4.7KΩ, Chip				uaa.	500.000	
R363 NI01823110 82KΩ ±1%, Chip R364 NI05472110 4.7KΩ, Chip				X201	FQ01205030	Seramic Vibrator 12.0MHz
R364 NI05472110 4.7KΩ, Chip						ł
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REF. DESIG.	PART NO.	DE	SCRIPTION
PY16	WB157K1420 ZZ157K8420	PY16-DISPLA P.W. Board, Di P.W. Board Ass	
CY02 CY04	DK58473300 DD55330300	PY16-CAPACI Ceramic Ceramic	0.047µF, Chip 33pF ±5%, Chip
CY05 CY07	DD55330300	Ceramic	33pF ±5%, Chip 2200pF ±10%, Chip
CY14	DK56222300	Ceramic	2200pr = 10%, 0mp
RY01		PY16-RESIST	
RY05 RY06	NI05154110	150KΩ	±5% 1/10W, Chip
RY13	NI05103110	- 10ΚΩ	±5% 1/10W, Chip
RY15 RY16	NI05101110 NI05332110	100Ω 3.3KΩ	±5% 1/10W, Chip ±5% 1/10W, Chip
RY17 RY18	NI05562110 NI05562110	5.6KΩ 5.6KΩ	±5% 1/10W, Chip ±5% 1/10W, Chip
RY19 RY20	NI05103110 NI05103110	10KΩ 10KΩ	±5% 1/10W, Chip ±5% 1/10W, Chip
RY21 RY24	NI05103110 NI05472110	10KΩ 4.7KΩ	±5% 1/10W, Chip ±5% 1/10W, Chip
RY25 RY26	NI05334110 NI05103110	330KΩ 10KΩ	±5% 1/10W, Chip
RY27	NI05103110	10KΩ PY16-SEMICO	±5% 1/10W, Chip
DY01 }	HZ20003020		AA151K, Chip
DY05 DY06	HZ20003020	Diode N	AA151K, Chip
QY01 QY02	HC10212030	IC L	.C6554D
QY06	BA10001020	Semicon Comp	oosit UN2114, Chip
QY10 QY11	HX413281S0 HX413281S0	Transistor 2	SD 1328(S), Chip SD 1328(S), Chip
QY12 QY13 QY14	HX327121A0 HX327121A0 HX327121A0	Transistor 2	SC2712(G), Chip SC2712(G), Chip SC2712(G), Chip
	1102/12100	11011313131	,
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REF. DESIG.	PART NO.	DESCRIPTION
		PY16-MISCELLANEOUS
JY02	A106006330	Jack, 13P
SY01 SY02	SP01010970 SP01010970	Push Switch, Stop Push Switch, Pause
SY03	SP01010970	Push Switch, Play
SY05 } SY16	SP01010970	Push Switch, Play
VY01	HQ30801410	Display Unit
WY01 WY03	YB00180330 YB00130360	Connective Cord, 13P Connective Cord, 5P
XY01 ZY01	FQ03004010 HW10001550	Seramic Vibrator 3.00MHz Photo Unit
21.00	14/2 4 5 5 14 4 4 4 5	PY26-LAMP CIRCUIT BOARD
PY26	WB157K1440 ZZ157K8440	P.W. Board, Lamp P.W. Board Assembly
DY51 DY52	HD20003000 HD20003000	Diode RL103E, etc. Diode RL103E, etc.
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(W01-99)	Assembly and Wiring
(T01-99)	Adjustment
(X01-00)	Correction

NOTE ON SAFETY:

Symbol & Fire or electrical shock hazard. Only original parts should be used to replace any part marked with symbol &. Any other component substitution (other than original type), may increase risk of fire or electrical shock hazard.

[MEMO]